

LZ2 Block Diagram

Project code: 91.4K101.001 ZY LZ2
91.4J301.001 XR LX2
PCB P/N : 08214-1
Revision : -1

PCB 8-LAYER STACKUP

TOP
GND
S
S
PWR
S
GND
BOTTOM

SYSTEM DC/DC TPS51120 36

INPUTS	OUTPUTS
DCBATOUT	5V_S5 3D3V_S5

SYSTEM DC/DC TPS51124 37

INPUTS	OUTPUTS
DCBATOUT	1D05V_S0 1D5V_S3

TPS51100 38

INPUTS	OUTPUTS
1D5V_S3	DDR_VREF_S0 (1.5A) DDR_VREF_S3

1D5V_S3 33

INPUTS	OUTPUTS
1D5V_S3	1D5V_S0

CHARGER BQ24740 39

INPUTS	OUTPUTS
DCBATOUT	CHG_PWR 18V UP+5V 5V 100mA

CPU DC/DC ADP3208 35

INPUTS	OUTPUTS
DCBATOUT	VCC_CORE

Mobile CPU Penryn SV 35W

CLK GEN. 3

EMC2102 07

Cantiga
AGTL+ CPU I/F
DDR Memory I/F
INTEGRATED GRAPHICS
LVDS, CRT I/F
8,9,10,11,12,13,14

ICH9M
6 PCIe ports
PCI/PCI BRIDGE
ACPI 1.1
4 SATA
12 USB
High Definition Audio
LPC I/F
Serial Peripheral I/F
19,20,21,22,23

Realtek RTS5158E Cardreader 28

SD/MMC/MS 3 in 1 28

LAN Boardcom 5906M 26

RJ45 27

Mini Card a/b/g/n 31

Codec ALC269 (include AMP) 25

MODEM MDC Card 24

RJ11

INT MIC

SPR x2

MIC In

HP

New card 31

Power switch 31

SATA-HDD 24

SATA-ODD 24

USB 3 Port 32

Finger Print 32

BlueTooth 24

CAMERA 17

KBC Winbond WPC776 29

G-sensor 30

Touch Pad 34

INT. KB 34

BIOS 2M byte 34

LPC DEBUG CONN. 24

PCB 8-LAYER STACKUP

TOP
GND
S
S
PWR
S
GND
BOTTOM

Wistron Corporation
21F, 8B, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

BLOCK DIAGRAM

LZ2

Date: Wednesday, May 28, 2008 Sheet 1 of 41

LZ2 Block Diagram

Project code: 91.4K101.001 ZY LZ2
91.4J301.001 XR LX2
PCB P/N : 08214-1
Revision : -1

SYSTEM DC/DC TPS51120 36

INPUTS	OUTPUTS
DCBATOUT	5V_S5 3D3V_S5

SYSTEM DC/DC TPS51124 37

INPUTS	OUTPUTS
DCBATOUT	1D05V_S0 1D5V_S3

TPS51100 38

INPUTS	OUTPUTS
1D5V_S3	DDR_VREF_S0 (1.5A) DDR_VREF_S3

CHARGER BQ24740 39

INPUTS	OUTPUTS
DCBATOUT	CHG_PWR 18V UP+5V 5V 100mA

CPU DC/DC ADP3208 35

INPUTS	OUTPUTS
DCBATOUT	VCC_CORE

PCB 8-LAYER STACKUP

TOP _____
GND _____
S _____
S _____
PWR _____
S _____
GND _____
BOTTOM _____

Mobile CPU Penryn SV 35W 4, 5

CLK GEN. 3

EMC2102 07

Host Bus 800/1066MHz@1.05V

Cantiga AGTL+ CPU I/F
DDR Memory I/F
INTEGRATED GRAPHICS
LVDS, CRT I/F
8, 9, 10, 11, 12, 13, 14

ICH9M 6 PCIe ports
PCI/PCI BRIDGE
ACPI 1.1
4 SATA
12 USB
High Definition Audio
LPC I/F
Serial Peripheral I/F
19, 20, 21, 22, 23

Realtek RTS5158E Cardreader 28

SD/MMC/MS 3 in 1 28

LAN Boardcom 5906M 26

RJ45 27

Mini Card a/b/g/n 31

Codec ALC269 (include AMP) 25

MODEM MDC Card 24

Finger Print 32

BlueTooth 24

KBC Winbond WPC776 29

G-sensor 30

Touch Pad 34

INT. KB 34

BIOS 2M byte 34

LPC DEBUG CONN. 24

USB 3 Port 32

SATA-HDD 24

SATA-ODD 24

New card 31

Power switch 31

Codecs and Peripherals:
INT MIC
SPR x2
MIC In
HP
RJ11

Connectors:
CRT 18
12"W LCD 17

Other components:
AZALIA
PCI Express / USB
CAMERA 17

LZ2 Block Diagram

Project code: 91.4K101.001 ZY LZ2
91.4J301.001 XR LX2
PCB P/N : 08214-1
Revision : -1

PCB 8-LAYER STACKUP

TOP
GND
S
S
PWR
S
GND
BOTTOM

SYSTEM DC/DC TPS51120 36

INPUTS	OUTPUTS
DCBATOUT	5V_S5 3D3V_S5

SYSTEM DC/DC TPS51124 37

INPUTS	OUTPUTS
DCBATOUT	1D05V_S0 1D5V_S3

TPS51100 38

INPUTS	OUTPUTS
1D5V_S3	DDR_VREF_S0 (1.5A) DDR_VREF_S3

1D5V_S3 33

INPUTS	OUTPUTS
1D5V_S3	1D5V_S0

CHARGER BQ24740 39

INPUTS	OUTPUTS
DCBATOUT	CHG_PWR 18V UP+5V 5V 100mA

CPU DC/DC ADP3208 35

INPUTS	OUTPUTS
DCBATOUT	VCC_CORE

Mobile CPU Penryn SV 35W

CLK GEN. 3

EMC2102 07

Cantiga
AGTL+ CPU I/F
DDR Memory I/F
INTEGRATED GRAHPICS
LVDS, CRT I/F
8,9,10,11,12,13,14

ICH9M
6 PCIe ports
PCI/PCI BRIDGE
ACPI 1.1
4 SATA
12 USB
High Definition Audio
LPC I/F
Serial Peripheral I/F
19,20,21,22,23

Realtek RTS5158E Cardreader 28

SD/MMC/MS 3 in 1 28

LAN Boardcom 5906M 26

RJ45 27

Mini Card a/b/g/n 31

Codec ALC269 (include AMP) 25

MODEM MDC Card 24

RJ11

INT MIC

SPR x2

MIC In

HP

New card 31

Power switch 31

Finger Print 32

BlueTooth 24

CAMERA 17

USB 3 Port 32

SATA-HDD 24

SATA-ODD 24

KBC Winbond WPC776 29

G-sensor 30

Touch Pad 34

INT. KB 34

BIOS 2M byte 34

LPC DEBUG CONN. 24

PCB 8-LAYER STACKUP

TOP
GND
S
S
PWR
S
GND
BOTTOM

Wistron Corporation
21F, 8B, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

BLOCK DIAGRAM

LZ2

Date: Wednesday, May 28, 2008 Sheet 1 of 41

LZ2 Block Diagram

Project code: 91.4K101.001 ZY LZ2
91.4J301.001 XR LX2
PCB P/N : 08214-1
Revision : -1

PCB 8-LAYER STACKUP

TOP _____
GND _____
S _____
S _____
PWR _____
S _____
GND _____
BOTTOM _____

SYSTEM DC/DC TPS51120 36

INPUTS	OUTPUTS
DCBATOUT	5V_S5 3D3V_S5

SYSTEM DC/DC TPS51124 37

INPUTS	OUTPUTS
DCBATOUT	1D05V_S0 1D5V_S3

TPS51100 38

INPUTS	OUTPUTS
1D5V_S3	DDR_VREF_S0 (1.5A) DDR_VREF_S3

1D5V_S3 33

INPUTS	OUTPUTS
1D5V_S3	1D5V_S0

CHARGER BQ24740 39

INPUTS	OUTPUTS
DCBATOUT	CHG_PWR 18V UP+5V 5V 100mA

CPU DC/DC ADP3208 35

INPUTS	OUTPUTS
DCBATOUT	VCC_CORE

Mobile CPU Penryn SV 35W 4, 5

CLK GEN. 3

EMC2102 07

Host Bus 800/1066MHz@1.05V

Cantiga 8, 9, 10, 11, 12, 13, 14

AGTL+ CPU I/F
DDR Memory I/F
INTEGRATED GRAPHICS
LVDS, CRT I/F

ICH9M 19, 20, 21, 22, 23

6 PCIe ports
PCI/PCI BRIDGE
ACPI 1.1
4 SATA
12 USB
High Definition Audio
LPC I/F
Serial Peripheral I/F

DDR3 socket 15

DDR3 socket 16

Codec ALC269 (include AMP) 25

INT MIC
SPR x2
MIC In
HP

MODEM MDC Card 24

RJ11

Realtek RTS5158E Cardreader 28

SD/MMC/MS 3 in 1 28

LAN Boardcom 5906M 26

RJ45 27

Mini Card a/b/g/n 31

USB 3 Port 32

Finger Print 32

BlueTooth 24

CAMERA 17

KBC Winbond WPC776 29

G-sensor 30
Touch Pad 34
INT. KB 34
BIOS 2M byte 34

LPC DEBUG CONN. 24

SATA-HDD 24

SATA-ODD 24

New card 31

PCI Express / USB

Power switch 31

Wistron Corporation
21F, 8B, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

BLOCK DIAGRAM

LZ2

Date: Wednesday, May 28, 2008 Sheet 1 of 41

LZ2 Block Diagram

Project code: 91.4K101.001 ZY LZ2
91.4J301.001 XR LX2
PCB P/N : 08214-1
Revision : -1

PCB 8-LAYER STACKUP

TOP _____
GND _____
S _____
S _____
PWR _____
S _____
GND _____
BOTTOM _____

SYSTEM DC/DC TPS51120 36

INPUTS	OUTPUTS
DCBATOUT	5V_S5 3D3V_S5

SYSTEM DC/DC TPS51124 37

INPUTS	OUTPUTS
DCBATOUT	1D05V_S0 1D5V_S3

TPS51100 38

INPUTS	OUTPUTS
1D5V_S3	DDR_VREF_S0 (1.5A) DDR_VREF_S3

CHARGER BQ24740 39

INPUTS	OUTPUTS
DCBATOUT	CHG_PWR 18V UP+5V 5V 100mA

CPU DC/DC ADP3208 35

INPUTS	OUTPUTS
DCBATOUT	VCC_CORE

Mobile CPU Penryn SV 35W 4, 5

CLK GEN. 3

EMC2102 07

Host Bus 800/1066MHz@1.05V

Cantiga 8, 9, 10, 11, 12, 13, 14

AGTL+ CPU I/F
DDR Memory I/F
INTEGRATED GRAPHICS
LVDS, CRT I/F

ICH9M 19, 20, 21, 22, 23

6 PCIe ports
PCI/PCI BRIDGE
ACPI 1.1
4 SATA
12 USB
High Definition Audio
LPC I/F
Serial Peripheral I/F

DDR3 socket 15

DDR3 socket 16

Codec ALC269 25 (include AMP)

INT MIC
SPR x2
MIC In
HP

MODEM MDC Card 24

RJ11

Realtek RTS5158E Cardreader 28

SD/MMC/MS 3 in 1 28

LAN Boardcom 5906M 26

RJ45 27

Mini Card 31 a/b/g/n

USB 3 Port 32

Finger Print 32

BlueTooth 24

CAMERA 17

KBC Winbond WPC776 29

G-sensor 30
Touch Pad 34
INT. KB 34
BIOS 2M byte 34

LPC DEBUG CONN. 24

SATA-HDD 24

SATA-ODD 24

New card 31

PCI Express / USB

Power switch 31

PCB 8-LAYER STACKUP

TOP _____
GND _____
S _____
S _____
PWR _____
S _____
GND _____
BOTTOM _____

Wistron Corporation
21F, 8B, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

BLOCK DIAGRAM

LZ2

Date: Wednesday, May 28, 2008 Sheet 1 of 41

LZ2 Block Diagram

Project code: 91.4K101.001 ZY LZ2
91.4J301.001 XR LX2
PCB P/N : 08214-1
Revision : -1

PCB 8-LAYER STACKUP

TOP _____
GND _____
S _____
S _____
PWR _____
S _____
GND _____
BOTTOM _____

SYSTEM DC/DC TPS51120 36

INPUTS	OUTPUTS
DCBATOUT	5V_S5 3D3V_S5

SYSTEM DC/DC TPS51124 37

INPUTS	OUTPUTS
DCBATOUT	1D05V_S0 1D5V_S3

TPS51100 38

INPUTS	OUTPUTS
1D5V_S3	DDR_VREF_S0 (1.5A) DDR_VREF_S3

1D5V_S3 33

INPUTS	OUTPUTS
1D5V_S3	1D5V_S0

CHARGER BQ24740 39

INPUTS	OUTPUTS
DCBATOUT	CHG_PWR 18V UP+5V 5V 100mA

CPU DC/DC ADP3208 35

INPUTS	OUTPUTS
DCBATOUT	VCC_CORE

Mobile CPU Penryn SV 35W 4, 5

CLK GEN. 3

EMC2102 07

Host Bus 800/1066MHz@1.05V

Cantiga 8, 9, 10, 11, 12, 13, 14
AGTL+ CPU I/F
DDR Memory I/F
INTEGRATED GRAPHICS
LVDS, CRT I/F

DDR3 socket 15
DDR3 socket 16

ICH9M 19, 20, 21, 22, 23
6 PCIe ports
PCI/PCI BRIDGE
ACPI 1.1
4 SATA
12 USB
High Definition Audio
LPC I/F
Serial Peripheral I/F

Codec ALC269 (include AMP) 25
AZALIA

Realtek RTS5158E Cardreader 28
USB

SD/MMC/MS 3 in 1 28

LAN Boardcom 5906M 26
PCIe

RJ45 27

Mini Card a/b/g/n 31
PCIe/ USB

LPC BUS

Codec ALC269 (include AMP) 25
INT MIC
SPR x2
MIC In
HP

MODEM MDC Card 24
RJ11

New card 31
PCI Express / USB

Power switch 31

SATA -HDD 24
SATA -ODD 24

USB 3 Port 32

Finger Print 32

BlueTooth 24

CAMERA 17

KBC Winbond WPC776 29
SPI I/F

G-sensor 30

Touch Pad 34

INT. KB 34

BIOS 2M byte 34

LPC DEBUG CONN. 24

Wistron Corporation
21F, 8B, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

BLOCK DIAGRAM

LZ2

SB

Date: Wednesday, May 28, 2008 Sheet 1 of 41

LZ2 Block Diagram

Project code: 91.4K101.001 ZY LZ2
91.4J301.001 XR LX2
PCB P/N : 08214-1
Revision : -1

PCB 8-LAYER STACKUP

TOP _____
GND _____
S _____
S _____
PWR _____
S _____
GND _____
BOTTOM _____

SYSTEM DC/DC TPS51120 36

INPUTS	OUTPUTS
DCBATOUT	5V_S5 3D3V_S5

SYSTEM DC/DC TPS51124 37

INPUTS	OUTPUTS
DCBATOUT	1D05V_S0 1D5V_S3

TPS51100 38

INPUTS	OUTPUTS
1D5V_S3	DDR_VREF_S0 (1.5A) DDR_VREF_S3

1D5V_S3 33

INPUTS	OUTPUTS
1D5V_S3	1D5V_S0

CHARGER BQ24740 39

INPUTS	OUTPUTS
DCBATOUT	CHG_PWR 18V UP+5V 5V 100mA

CPU DC/DC ADP3208 35

INPUTS	OUTPUTS
DCBATOUT	VCC_CORE

Mobile CPU Penryn SV 35W

CLK GEN. 3

EMC2102 07

Cantiga
AGTL+ CPU I/F
DDR Memory I/F
INTEGRATED GRAHPICS
LVDS, CRT I/F
8,9,10,11,12,13,14

ICH9M
6 PCIe ports
PCI/PCI BRIDGE
ACPI 1.1
4 SATA
12 USB
High Definition Audio
LPC I/F
Serial Peripheral I/F
19,20,21,22,23

Realtek RTS5158E Cardreader 28

SD/MMC/MS 3 in 1 28

LAN Boardcom 5906M 26

RJ45 27

Mini Card a/b/g/n 31

Codec ALC269 (include AMP) 25

INT MIC

SPR x2

MIC In

HP

MODEM MDC Card 24

RJ11

New card 31

Power switch 31

Finger Print 32

BlueTooth 24

CAMERA 17

USB 3 Port 32

SATA-HDD 24

SATA-ODD 24

KBC Winbond WPC776 29

G-sensor 30

Touch Pad 34

INT. KB 34

BIOS 2M byte 34

LPC DEBUG CONN. 24

PCB 8-LAYER STACKUP

TOP _____
GND _____
S _____
S _____
PWR _____
S _____
GND _____
BOTTOM _____

Wistron Corporation
21F, 8B, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

BLOCK DIAGRAM

LZ2

Date: Wednesday, May 28, 2008 Sheet 1 of 41

LZ2 Block Diagram

Project code: 91.4K101.001 ZY LZ2
91.4J301.001 XR LX2
PCB P/N : 08214-1
Revision : -1

PCB 8-LAYER STACKUP

TOP _____
GND _____
S _____
S _____
PWR _____
S _____
GND _____
BOTTOM _____

SYSTEM DC/DC TPS51120 36

INPUTS	OUTPUTS
DCBATOUT	5V_S5 3D3V_S5

SYSTEM DC/DC TPS51124 37

INPUTS	OUTPUTS
DCBATOUT	1D05V_S0 1D5V_S3

TPS51100 38

INPUTS	OUTPUTS
1D5V_S3	DDR_VREF_S0 (1.5A) DDR_VREF_S3

1D5V_S3 33

INPUTS	OUTPUTS
1D5V_S3	1D5V_S0

CHARGER BQ24740 39

INPUTS	OUTPUTS
DCBATOUT	CHG_PWR 18V UP+5V 5V 100mA

CPU DC/DC ADP3208 35

INPUTS	OUTPUTS
DCBATOUT	VCC_CORE

Mobile CPU Penryn SV 35W 4, 5

CLK GEN. 3

EMC2102 07

Host Bus 800/1066MHz@1.05V

Cantiga 8, 9, 10, 11, 12, 13, 14

AGTL+ CPU I/F
DDR Memory I/F
INTEGRATED GRAPHICS
LVDS, CRT I/F

ICH9M 19, 20, 21, 22, 23

6 PCIe ports
PCI/PCI BRIDGE
ACPI 1.1
4 SATA
12 USB
High Definition Audio
LPC I/F
Serial Peripheral I/F

DDR3 socket 15

DDR3 socket 16

Codec ALC269 (include AMP) 25

INT MIC
SPR x2
MIC In
HP

MODEM MDC Card 24

RJ11

Realtek RTS5158E Cardreader 28

SD/MMC/MS 3 in 1 28

LAN Boardcom 5906M 26

RJ45 27

Mini Card a/b/g/n 31

USB 3 Port 32

Finger Print 32

BlueTooth 24

CAMERA 17

KBC Winbond WPC776 29

G-sensor 30
Touch Pad 34
INT. KB 34
BIOS 2M byte 34

LPC DEBUG CONN. 24

SATA-HDD 24

SATA-ODD 24

New card 31

PCI Express / USB

Power switch 31

Wistron Corporation
21F, 8B, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

BLOCK DIAGRAM

LZ2

Date: Wednesday, May 28, 2008 Sheet 1 of 41

ICH9M Functional Strap Definitions

ICH9 EDS 642879 Rev.1.5

Signal	Usage/when Sampled	Comment
HDA_SDOUT	XOR Chain Entrance/ PCIE Port Config1 bit1, Rising Edge of PWROK	Allows entrance to XOR Chain testing when TP3 pulled low.When TP3 not pulled low at rising edge of PWROK,sets bit1 of RPC.PC(Config Registers: offset 224h). This signal has weak internal pull-down
HDA_SYNC	PCIE config1 bit0, Rising Edge of PWROK.	This signal has a weak internal pull-down. Sets bit0 of RPC.PC(Config Registers:Offset 224h)
GNT2#/ GPIO53	PCIE config2 bit2, Rising Edge of PWROK.	This signal has a weak internal pull-up. Sets bit2 of RPC.PC2(Config Registers:Offset 0224h)
GPIO20	Reserved Rising Edge of PWROK.	This signal has a weak internal pull-down. Note:This signal should not be pulled high.
GNT1#/ GPIO51	ESI Strap(Server Only) Rising edge of PWROK	Tying this strap low configures DMI for SiCompatible operation. This signal has a weak internal pull-up. NOTE: ESI compatible mode is for server latforms only. This signal should not be pulled low for desktop and mobile.
GNT3#/ GPIO55	Top-Block Swap Override. Rising Edge of PWROK.	Sampled low:Top-Block Swap mode(inverts A16 for all cycles targeting FWH BIOS space). Note: Software will not be able to clear the Top-Swap bit until the system is rebooted without GNT3# being pulled down.
GNT0#: SPI_CS1#/ GPIO58	Boot BIOS Destination Selection 0:1. Rising Edge of PWROK.	Controllable via Boot BIOS Destination bit (Config Registers:Offset 3410h:bit 11:10). GNT0# is MSB, 01-SPI, 10-PCI, 11-LPC.
SPI_MOSI	Integrated TPM Enable, Rising Edge of CLPWROK	Sample low: the Integrated TPM will be disabled. Sample high: the MCH TPM enable strap is sampled low and the TPM disable bit is clear, the Integrated TPM will be enable.
GPIO49	DMI Termination Voltage, Rising Edge of PWROK.	The signal is required to be low for desktop applications and required to be high for mobile applications.
SATALED#	PCI Express Lane Reversal. Rising Edge of PWROK.	Signal has weak internal pull-up. Sets bit 27 of MPC.LR(Device 28:Function 0:Offset D8)
SPKR	No Reboot. Rising Edge of PWROK.	If sampled high, the system is strapped to the "No Reboot" mode(ICH9 will disable the TCO Timer system reboot feature). The status is readable via the NO REBOOT bit.
TP3	XOR Chain Entrance. Rising Edge of PWROK.	This signal should not be pull low unless using XOR chain testing.
GPIO33/ HDA_DOCK _EN#	Flash Descriptor Security Override Strap Rising Edge of PWROK	Sampled low:the Flash Descriptor Security will be overridden. If high,the security measures will be in effect.This should only be enabled in manufacturing environments using an external pull-up resistor.

ICH9M Integrated Pull-up and Pull-down Resistors

ICH9 EDS 642879 Rev.1.5

SIGNAL	Resistor Type/Value
CL_CLK[1:0]	PULL-UP 20K
CL_DATA[1:0]	PULL-UP 20K
CL_RST0#	PULL-UP 20K
DPRSLPVR/GPIO16	PULL-DOWN 20K
ENERGY_DETECT	PULL-UP 20K
HDA_BIT_CLK	PULL-DOWN 20K
HDA_DOCK_EN#/GPIO33	PULL-UP 20K
HDA_RST#	PULL-DOWN 20K
HDA_SDIN[3:0]	PULL-DOWN 20K
HDA_SDOUT	PULL-DOWN 20K
HDA_SYNC	PULL-DOWN 20K
GLAN_DOCK#	The pull-up or pull-down active when configured for native GLAN DOCK# functionality and determined by LAN controller
GNT[3:0]#/GPIO[55,53,51]	PULL-UP 20K
GPIO[20]	PULL-DOWN 20K
GPIO[49]	PULL-UP 20K
LDA[3:0]#/FWH[3:0]#	PULL-UP 20K
LAN_RXD[2:0]	PULL-UP 20K
LDRQ[0]	PULL-UP 20K
LDRQ[1]/GPIO23	PULL-UP 20K
PME#	PULL-UP 20K
PWRBTN#	PULL-UP 20K
SATALED#	PULL-UP 15K
SPI_CS1#/GPIO58/CLGPIO6	PULL-UP 20K
SPI_MISO	PULL-UP 20K
SPKR	PULL-DOWN 20K
TACH [3:0]	PULL-UP 20K
TP[3]	PULL-UP 20K
USB[11:0][P,N]	PULL-DOWN 15K

Cantiga chipset and ICH9M I/O controller Hub strapping configuration

Montevina Platform Design guide 22339 0.5
page 218

Pin Name	Strap Description	Configuration
CFG[2:0]	FSB Frequency Select	000 = FSB1067 011 = FSB667 010 = FSB800 others = Reserved
CFG[4:3] CFG8 CFG11 CFG[15:14] CFG[10:17]	Reserved	
CFG5	DMI x2 Select	0 = DMI x2 1 = DMI x4 (default)
CFG6	iTPM Host Interface	0= The iTPM Host Interface is enabled(Note2) 1= The iTPM Host Interface is disabled(default)
CFG7	Intel Management engine Crypto strap	0 = Transport Layer Security (TLS) cipher suite with no confidentiality 1 = TLS cipher suite with confidentiality (default)
CFG9	PCIE Graphics Lane	0 = Reverse Lanes,15->0,14->1 ect.. 1= Normal operation(Default):Lane Numbered in order
CFG10	PCIE Loopback enable	0 = Enable (Note 3) 1= Disabled (default)
CFG[13:12]	XOR/ALL	00 = Reserve 01 = XOR mode Enabled 01 = ALLZ mode Enabled (Note 3) 11 = Disabled (default)
CFG16	FSB dynamic ODT	0 = Dynamic ODT Disabled 1 = Dynamic ODT Enabled (Default)
CFG19	DMI Lane Reversal	0 = Normal operation(Default): Lane Numbered in order 1 = Reverse Lanes DMI x4 mode[MCH -> ICH]:(3->0,2->1,2->and0->3) DMI x2 mode[MCH -> ICH]:(3->0,2->1)
CFG20	Digital Display Port (SDVO/DP/iHDMI) Concurrent with PCIE	0 = Only Digital Display Port or PCIE is operational (Default) 1 =Digital display Port and PCIE are operating simultaneously via the PEG port
SDVO_CTRLDATA	SDVO Present	0 = No SDVO Card Present (Default) 1 = SDVO Card Present
LDDC_DATA	Local Flat Panel (LFP) Present	0 = LFP Disabled (default) 1= LFP Card Present; PCIE disabled

NOTE:

- All strap signals are sampled with respect to the leading edge of the (G)MCH Power OK (PWROK) signal.
- iTPM can be disabled by a 'Soft-Strap' option in the Flash-descriptor section of the Firmware. This 'Soft-Strap' is activated only after enabling iTPM via CFG6. Only one of the CFG10/CFG12/CFG13 straps can be enabled at any time.

PCIE Routing

LANE1	BroadCom LAN
LANE2	MiniCard WLAN
LANE4	NewCard

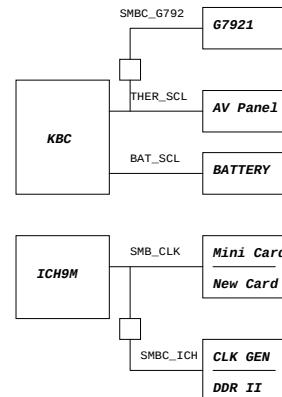
History:

LAB: 2008/01/02

USB Table

USB	
Pair	Device
0	JACK0
1	NC
2	JACK2
3	NC
4	BLUETOOTH
5	JACK1
6	Finger Print
7	Mini Card
8	CAMERA
9	NEW CARD
10	CARDREADER
11	NC

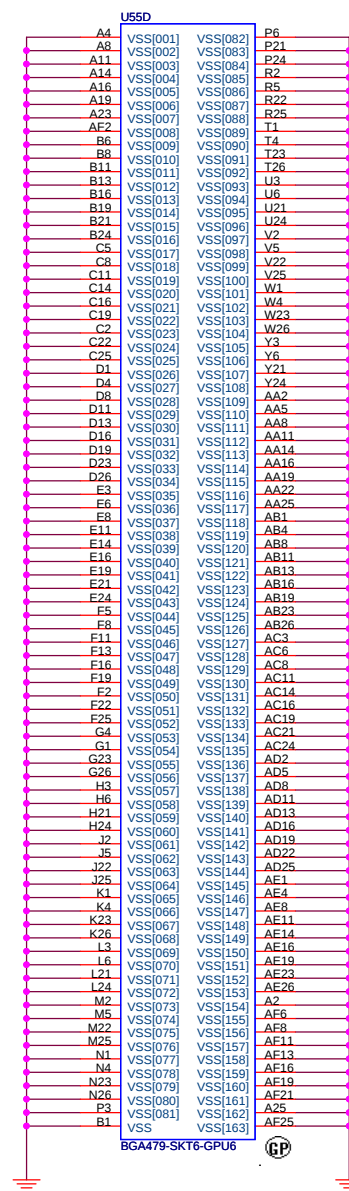
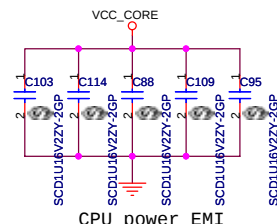
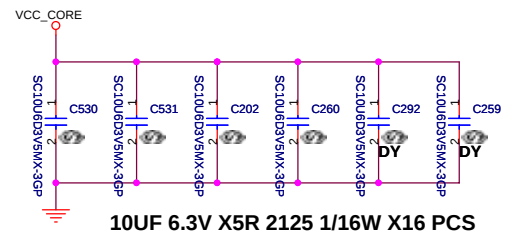
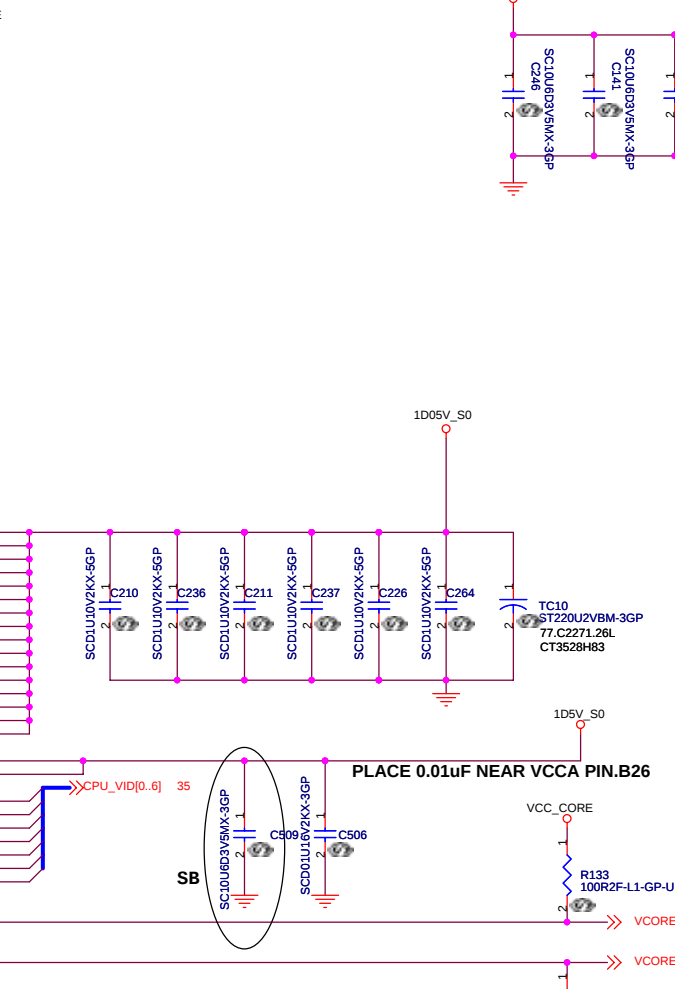
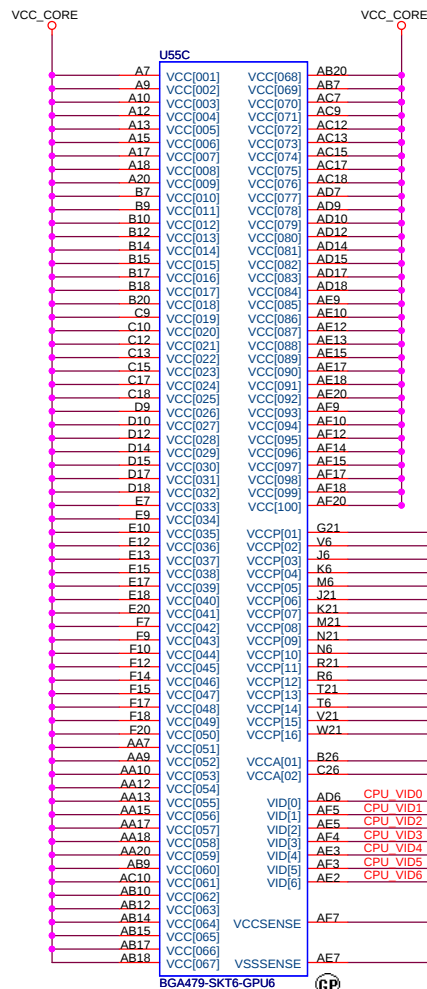
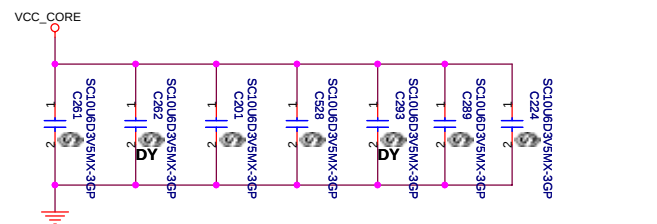
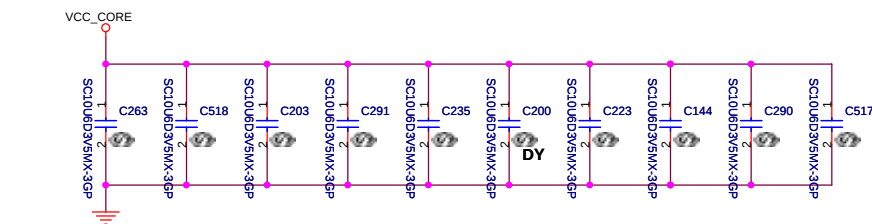
SBUS



17,33,35,36,37,39,41	DCBATOUT	DCBATOUT
7,19,29,34,36,39,40	SD3V_AUX_S5	SD3V_AUX_S5
7,31,33,36,39	5V_AUX_S5	5V_AUX_S5
17,20,21,22,23,24,26,29,30,31,33,34,36,37,41	SD3V_S5	SD3V_S5
22,32,33,36,37,38,41	5V_S5	5V_S5
10,12,13,15,16,33,37,38,41	ID5V_S3	ID5V_S3
15,16,38	OD75V_S3	OD75V_S3
13,33,38	ID8V_S0	ID8V_S0
3,7,10,11,13,15,16,17,18,19,20,21,22,23,24,25,26,29,31,32,33,34,35,36,37,38,41	SD3V_S0	SD3V_S0
7,13,17,18,22,23,24,25,33,34,35,41	5V_S0	5V_S0
4,5,6,8,10,11,12,13,19,22,33,37	ID05V_S0	ID05V_S0
3,5,13,19,20,22,31,33	ID5V_S0	ID5V_S0

<Variant Name>

Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
File	
Reference	
Size C	Document Number L72
Date: Thursday, June 05, 2008	Sheet 2 of 41



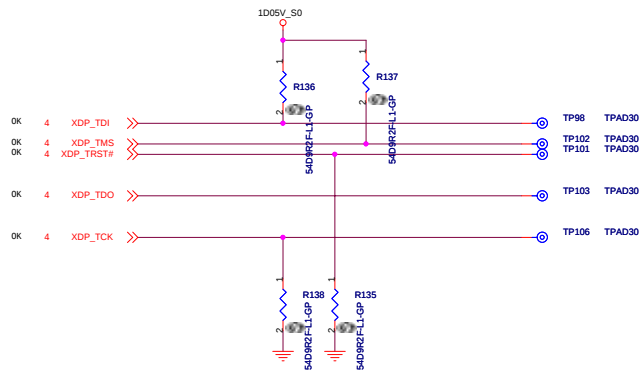
PLACE 0.01uF NEAR VCCA PIN.B26

<Variant Name>

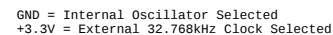
緯創資通

Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

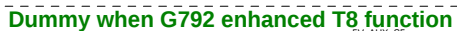
Title			Rev
Penryn CPU(2/2)			SB
Size	Document Number	LZ2	
A3			
Date:	Thursday, June 05, 2008	Sheet	5 of 41



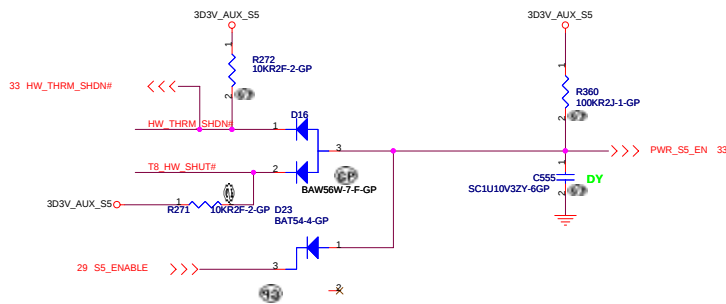
Layout notice : Both DN3 and DP3 routing
10 mil trace width and 10 mil spacing



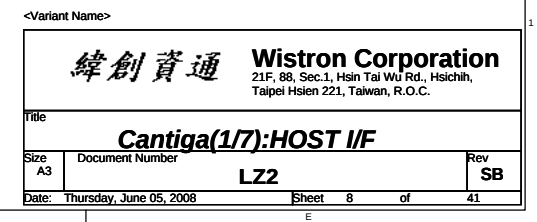
```
TRIP_SET Pin Voltage
V_DEGREE
=((Degree-75)/21)
```



HW thermal shut down tempature setting 95 degree . Put Near CPU .



Title			
Thermal/Fan Controller EMC2102			
Size Custom	Document Number	Rev	
	L72	SE	
Date: Thursday, June 05, 2008	Sheet 7	of	41



15 M_A_DQ[63..0] <<>>
15 M_A_DM[7..0] <<>>
15 M_A_DQS[7..0] <<>>
15 M_A_DQS# [7..0] <<>>
15 M_A_A[14..0] <<>>

16 M_B_DQ[63..0] <<>>
16 M_B_DM[7..0] <<>>
16 M_B_DQS[7..0] <<>>
16 M_B_DQS# [7..0] <<>>
16 M_B_A[14..0] <<>>

U56D			4 OF 16
M_A_DQ0	AJ38	SA_DQ_0	BD21
M_A_DQ1	AJ38	SA_DQ_1	SA_BS_0
M_A_DQ2	AN38	SA_DQ_2	AT25
M_A_DQ3	AM38	SA_DQ_3	SA_BS_1
M_A_DQ4	AJ38	SA_DQ_4	SA_BS_2
M_A_DQ5	AJ40	SA_DQ_5	SA_BS_3
M_A_DQ6	AM44	SA_DQ_6	SA_BS_4
M_A_DQ7	AJ40	SA_DQ_7	SA_BS_5
M_A_DQ8	AN43	SA_DQ_8	SA_BS_6
M_A_DQ9	AN44	SA_DQ_9	SA_BS_7
M_A_DQ10	AJ40	SA_DQ_10	SA_BS_8
M_A_DQ11	AT38	SA_DQ_11	SA_BS_9
M_A_DQ12	AN41	SA_DQ_12	SA_BS_10
M_A_DQ13	AN39	SA_DQ_13	SA_BS_11
M_A_DQ14	AJ44	SA_DQ_14	SA_BS_12
M_A_DQ15	AJ42	SA_DQ_15	SA_BS_13
M_A_DQ16	AV39	SA_DQ_16	SA_BS_14
M_A_DQ17	AY44	SA_DQ_17	SA_BS_15
M_A_DQ18	BA40	SA_DQ_18	SA_BS_16
M_A_DQ19	BD43	SA_DQ_19	SA_BS_17
M_A_DQ20	AV41	SA_DQ_20	SA_BS_18
M_A_DQ21	AY43	SA_DQ_21	SA_BS_19
M_A_DQ22	BB41	SA_DQ_22	SA_BS_20
M_A_DQ23	BC40	SA_DQ_23	SA_BS_21
M_A_DQ24	AY37	SA_DQ_24	SA_BS_22
M_A_DQ25	BD38	SA_DQ_25	SA_BS_23
M_A_DQ26	AV37	SA_DQ_26	SA_BS_24
M_A_DQ27	AT36	SA_DQ_27	SA_BS_25
M_A_DQ28	AY38	SA_DQ_28	SA_BS_26
M_A_DQ29	BB38	SA_DQ_29	SA_BS_27
M_A_DQ30	AY36	SA_DQ_30	SA_BS_28
M_A_DQ31	AW36	SA_DQ_31	SA_BS_29
M_A_DQ32	BD13	SA_DQ_32	SA_BS_30
M_A_DQ33	AJ11	SA_DQ_33	SA_BS_31
M_A_DQ34	BC11	SA_DQ_34	SA_BS_32
M_A_DQ35	BA12	SA_DQ_35	SA_BS_33
M_A_DQ36	AJ13	SA_DQ_36	SA_BS_34
M_A_DQ37	AV13	SA_DQ_37	SA_BS_35
M_A_DQ38	BD12	SA_DQ_38	SA_BS_36
M_A_DQ39	BC12	SA_DQ_39	SA_BS_37
M_A_DQ40	BB9	SA_DQ_40	SA_BS_38
M_A_DQ41	BA9	SA_DQ_41	SA_BS_39
M_A_DQ42	AJ10	SA_DQ_42	SA_BS_40
M_A_DQ43	AV9	SA_DQ_43	SA_BS_41
M_A_DQ44	BA11	SA_DQ_44	SA_BS_42
M_A_DQ45	BD9	SA_DQ_45	SA_BS_43
M_A_DQ46	AV8	SA_DQ_46	SA_BS_44
M_A_DQ47	BA6	SA_DQ_47	SA_BS_45
M_A_DQ48	AV5	SA_DQ_48	SA_BS_46
M_A_DQ49	AV7	SA_DQ_49	SA_BS_47
M_A_DQ50	AT9	SA_DQ_50	SA_BS_48
M_A_DQ51	AN8	SA_DQ_51	SA_BS_49
M_A_DQ52	AJ6	SA_DQ_52	SA_BS_50
M_A_DQ53	AJ6	SA_DQ_53	SA_BS_51
M_A_DQ54	AT5	SA_DQ_54	SA_BS_52
M_A_DQ55	AN10	SA_DQ_55	SA_BS_53
M_A_DQ56	AM11	SA_DQ_56	SA_BS_54
M_A_DQ57	AM5	SA_DQ_57	SA_BS_55
M_A_DQ58	AJ9	SA_DQ_58	SA_BS_56
M_A_DQ59	AJ8	SA_DQ_59	SA_BS_57
M_A_DQ60	AN12	SA_DQ_60	SA_BS_58
M_A_DQ61	AM13	SA_DQ_61	SA_BS_59
M_A_DQ62	AJ11	SA_DQ_62	SA_BS_60
M_A_DQ63	AJ12	SA_DQ_63	SA_BS_61

CANTIGA-GM-GP-U-NF

DDR SYSTEM MEMORY A

U56E			5 OF 16
M_B_DQ0	AK47	SB_DQ_0	BC16
M_B_DQ1	AK46	SB_DQ_1	BC17
M_B_DQ2	AP47	SB_DQ_2	BC33
M_B_DQ3	AP46	SB_DQ_3	M_B_BS0
M_B_DQ4	AJ46	SB_DQ_4	M_B_BS1
M_B_DQ5	AJ48	SB_DQ_5	M_B_BS2
M_B_DQ6	AM48	SB_DQ_6	M_B_BS3
M_B_DQ7	AP48	SB_DQ_7	M_B_BS4
M_B_DQ8	AJ47	SB_DQ_8	M_B_BS5
M_B_DQ9	AJ46	SB_DQ_9	M_B_BS6
M_B_DQ10	RA48	SB_DQ_10	M_B_BS7
M_B_DQ11	AY48	SB_DQ_11	M_B_BS8
M_B_DQ12	AT47	SB_DQ_12	M_B_BS9
M_B_DQ13	AK47	SB_DQ_13	M_B_BS10
M_B_DQ14	BA47	SB_DQ_14	M_B_BS11
M_B_DQ15	BC47	SB_DQ_15	M_B_BS12
M_B_DQ16	BC46	SB_DQ_16	M_B_BS13
M_B_DQ17	BC44	SB_DQ_17	M_B_BS14
M_B_DQ18	BC43	SB_DQ_18	M_B_BS15
M_B_DQ19	BE43	SB_DQ_19	M_B_BS16
M_B_DQ20	BE45	SB_DQ_20	M_B_BS17
M_B_DQ21	BC41	SB_DQ_21	M_B_BS18
M_B_DQ22	BE40	SB_DQ_22	M_B_BS19
M_B_DQ23	BF41	SB_DQ_23	M_B_BS20
M_B_DQ24	BC38	SB_DQ_24	M_B_BS21
M_B_DQ25	BE38	SB_DQ_25	M_B_BS22
M_B_DQ26	BH35	SB_DQ_26	M_B_BS23
M_B_DQ27	BH36	SB_DQ_27	M_B_BS24
M_B_DQ28	BH37	SB_DQ_28	M_B_BS25
M_B_DQ29	BH38	SB_DQ_29	M_B_BS26
M_B_DQ30	BH39	SB_DQ_30	M_B_BS27
M_B_DQ31	BH40	SB_DQ_31	M_B_BS28
M_B_DQ32	BH41	SB_DQ_32	M_B_BS29
M_B_DQ33	BH42	SB_DQ_33	M_B_BS30
M_B_DQ34	BH43	SB_DQ_34	M_B_BS31
M_B_DQ35	BH44	SB_DQ_35	M_B_BS32
M_B_DQ36	BH45	SB_DQ_36	M_B_BS33
M_B_DQ37	BH46	SB_DQ_37	M_B_BS34
M_B_DQ38	BH47	SB_DQ_38	M_B_BS35
M_B_DQ39	BH48	SB_DQ_39	M_B_BS36
M_B_DQ40	BH49	SB_DQ_40	M_B_BS37
M_B_DQ41	BH50	SB_DQ_41	M_B_BS38
M_B_DQ42	BH51	SB_DQ_42	M_B_BS39
M_B_DQ43	BH52	SB_DQ_43	M_B_BS40
M_B_DQ44	BH53	SB_DQ_44	M_B_BS41
M_B_DQ45	BH54	SB_DQ_45	M_B_BS42
M_B_DQ46	BH55	SB_DQ_46	M_B_BS43
M_B_DQ47	BH56	SB_DQ_47	M_B_BS44
M_B_DQ48	BH57	SB_DQ_48	M_B_BS45
M_B_DQ49	BH58	SB_DQ_49	M_B_BS46
M_B_DQ50	BH59	SB_DQ_50	M_B_BS47
M_B_DQ51	BH60	SB_DQ_51	M_B_BS48
M_B_DQ52	BH61	SB_DQ_52	M_B_BS49
M_B_DQ53	BH62	SB_DQ_53	M_B_BS50
M_B_DQ54	BH63	SB_DQ_54	M_B_BS51
M_B_DQ55	BH64	SB_DQ_55	M_B_BS52
M_B_DQ56	BH65	SB_DQ_56	M_B_BS53
M_B_DQ57	BH66	SB_DQ_57	M_B_BS54
M_B_DQ58	BH67	SB_DQ_58	M_B_BS55
M_B_DQ59	BH68	SB_DQ_59	M_B_BS56
M_B_DQ60	BH69	SB_DQ_60	M_B_BS57
M_B_DQ61	BH70	SB_DQ_61	M_B_BS58
M_B_DQ62	BH71	SB_DQ_62	M_B_BS59
M_B_DQ63	AJ3	SB_DQ_63	M_B_BS60

CANTIGA-GM-GP-U-NF

DDR SYSTEM MEMORY B

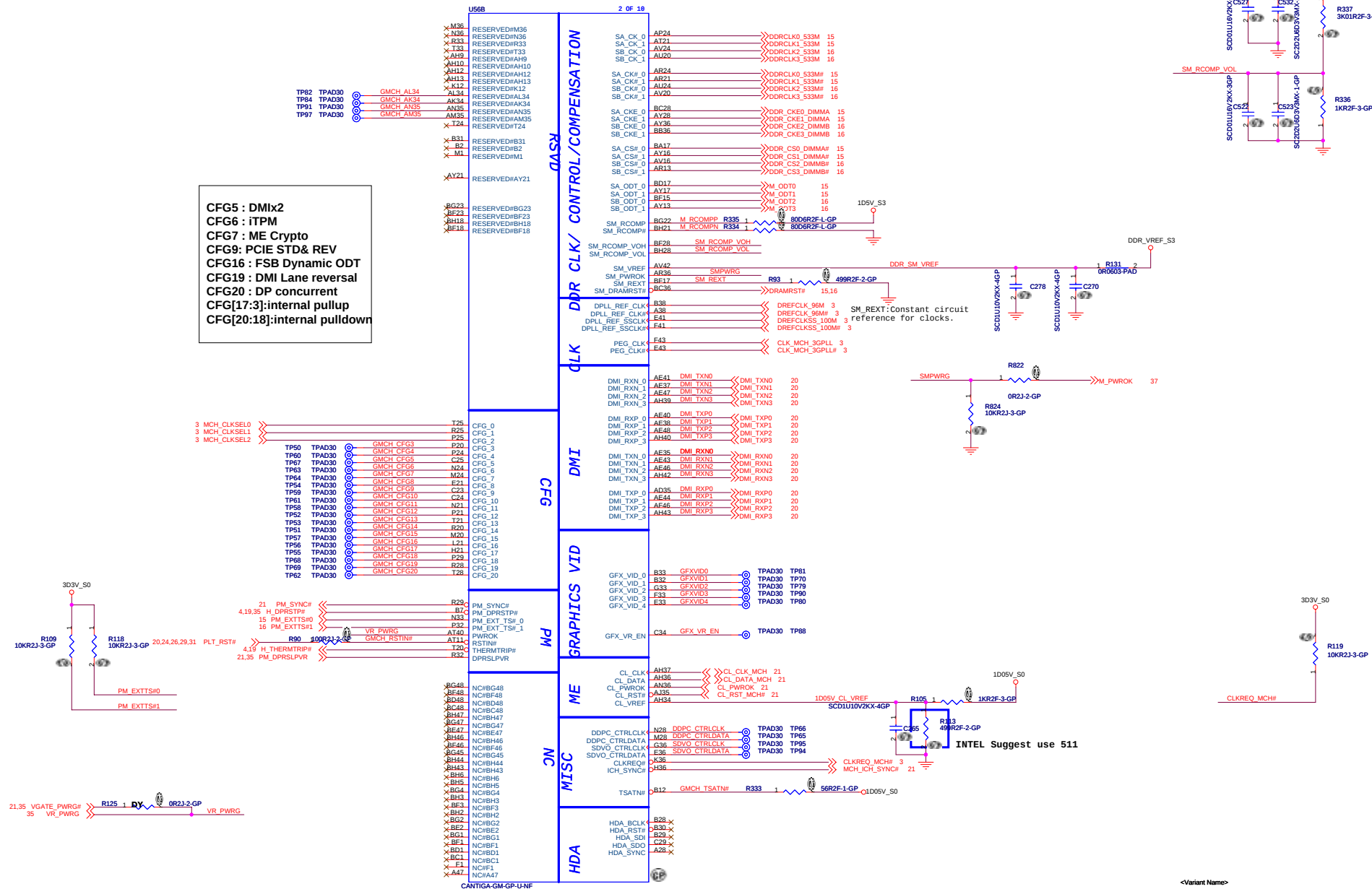
<Variant Name>

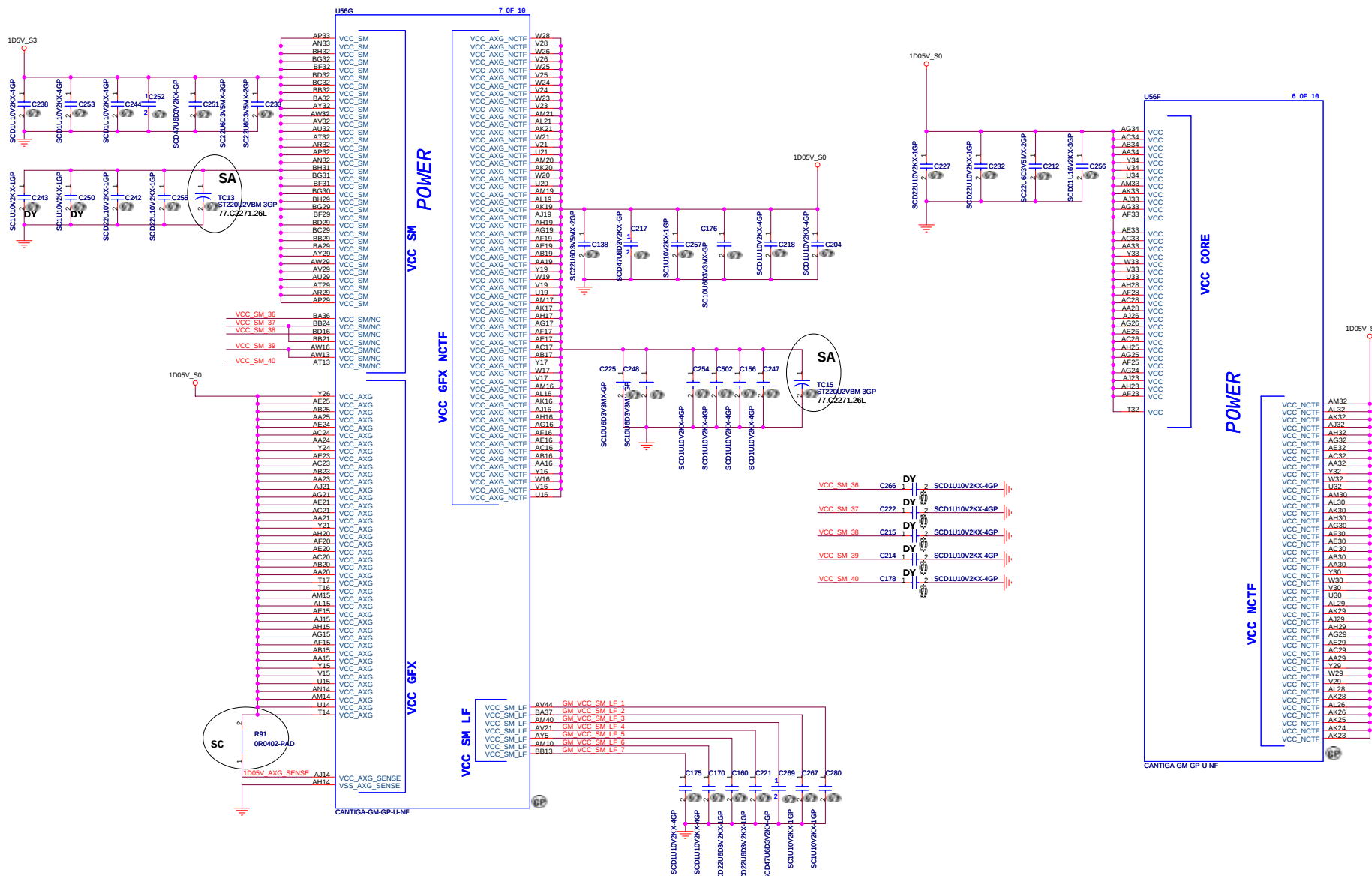
Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title	
Cantiga(2/7):DDR3	
Size	Document Number
C	LZ2
Date	Thursday, June 05, 2008
Sheet	9 of 41
Rev	SB

ME DEBUG PORT PIN OUT TABLE

RESERVED#AL34	ME_JTAG_TCK
RESERVED#AK34	ME_JTAG_TDI
RESERVED#AN35	ME_JTAG_TDO
RESERVED#AM35	ME_JTAG_TMS

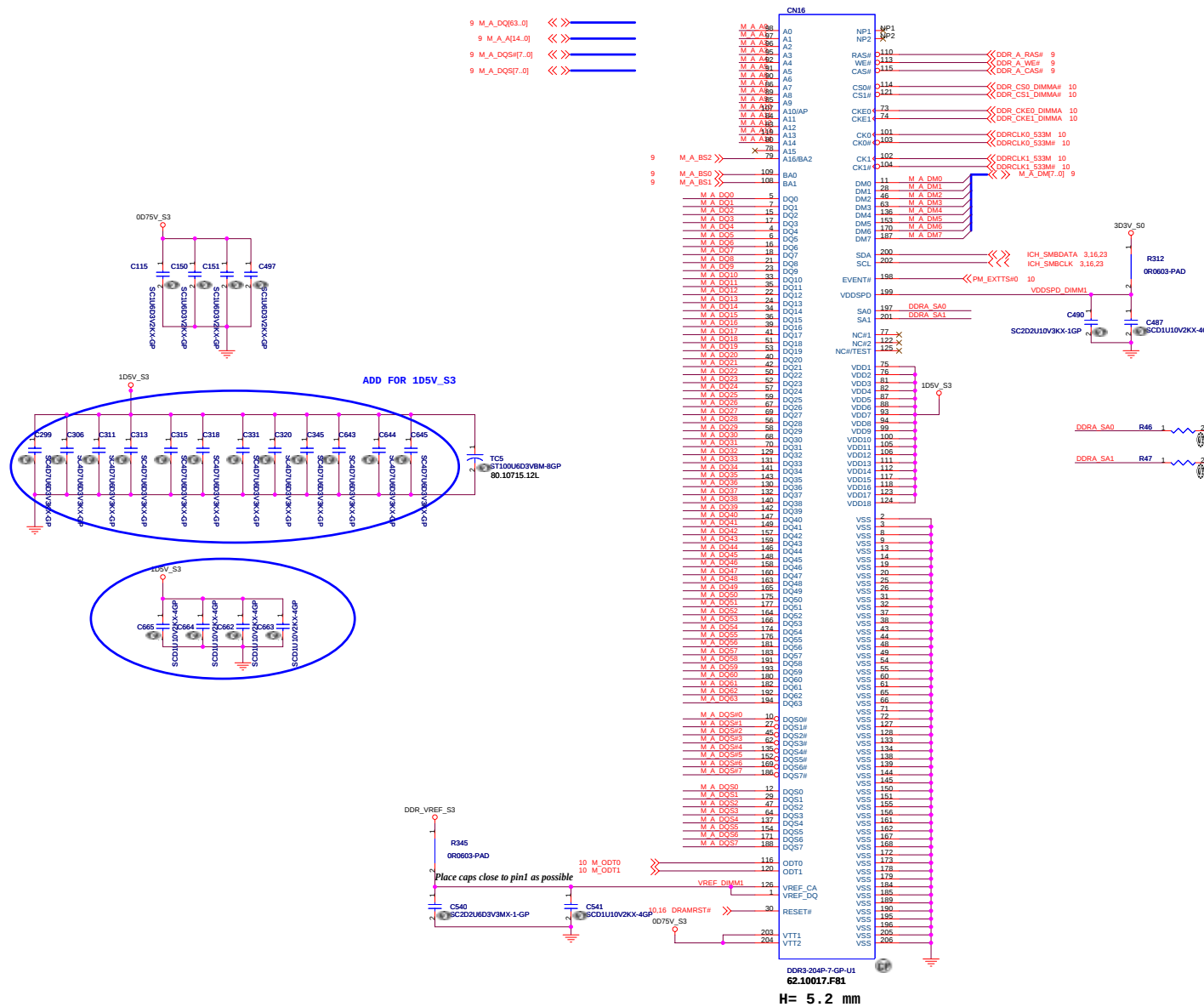
CFG5 : DMiX2
CFG6 : iTPM
CFG7 : ME Crypto
CFG9: PCIE STD& REV
CFG16 : FSB Dynamic ODT
CFG19 : DMI Lane reversal
CFG20 : DP concurrent
CFG[17:3]:internal pullup
CFG[20:18]:internal pulldown

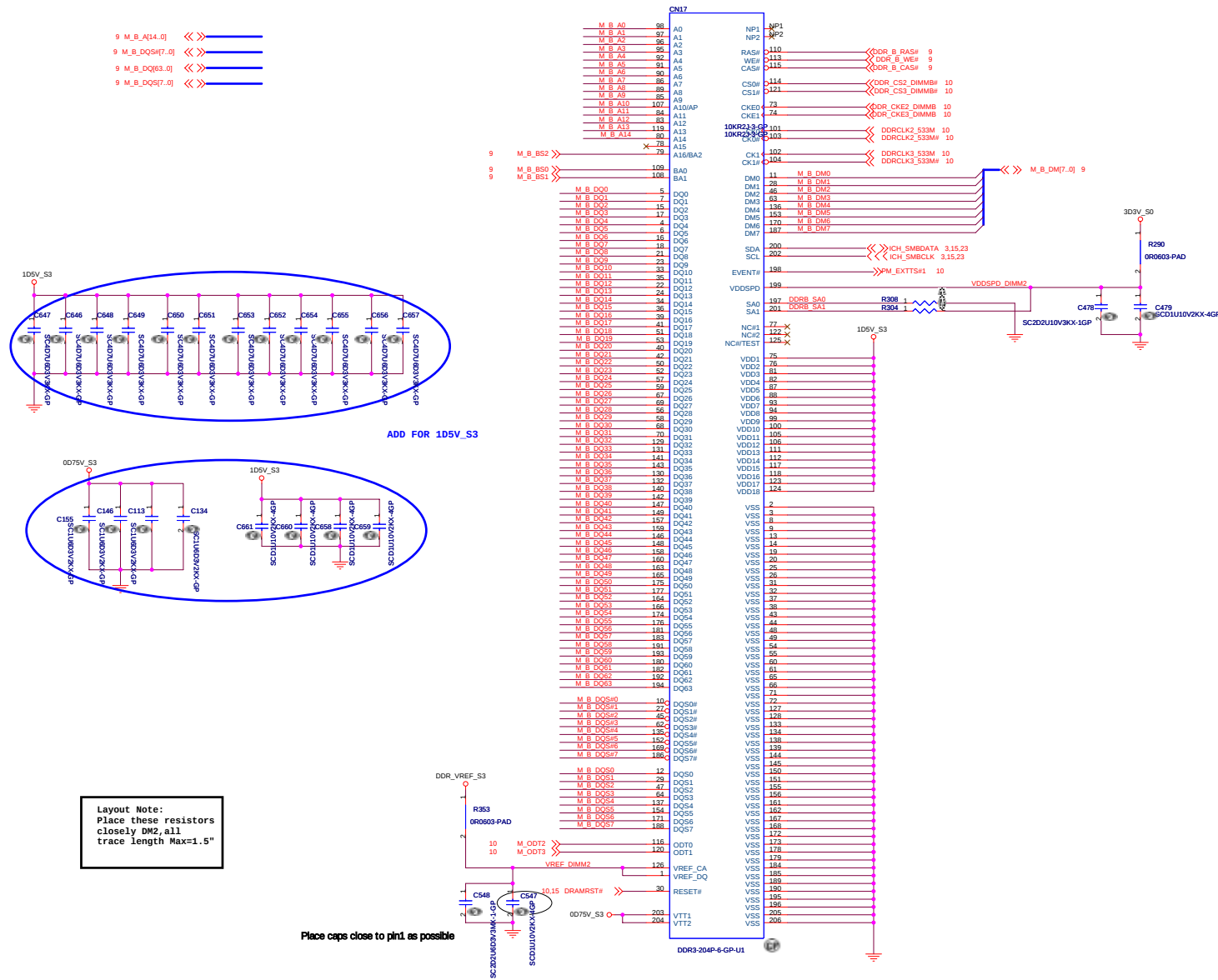


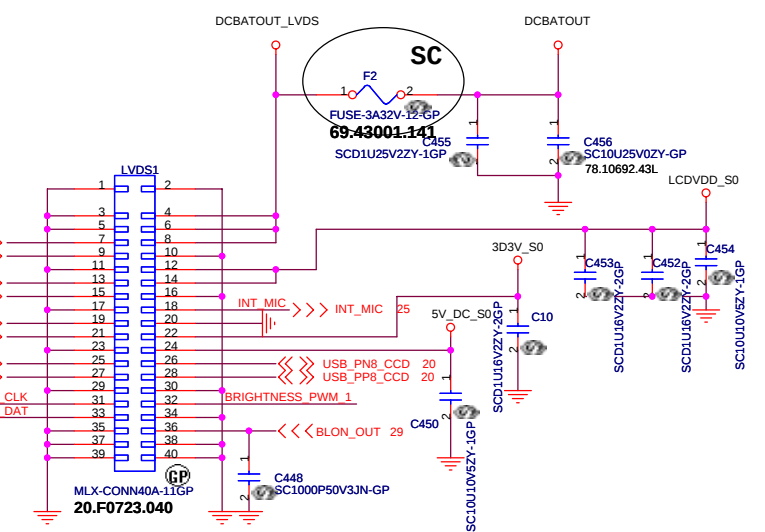
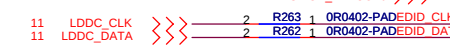
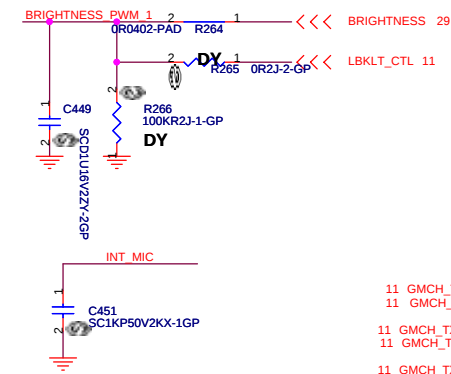
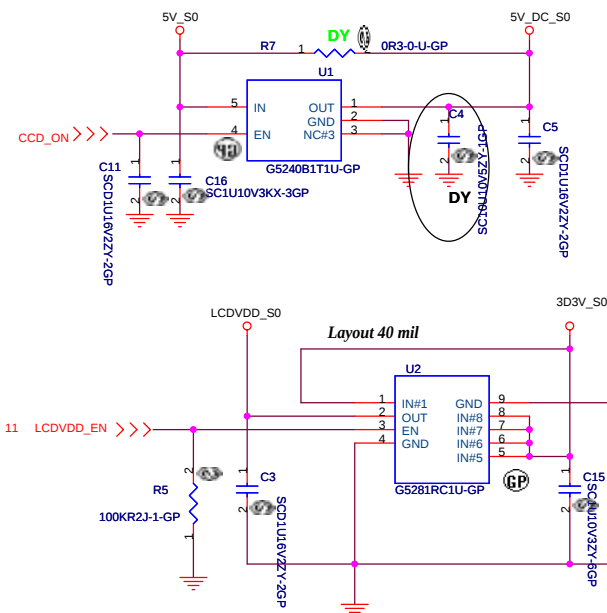




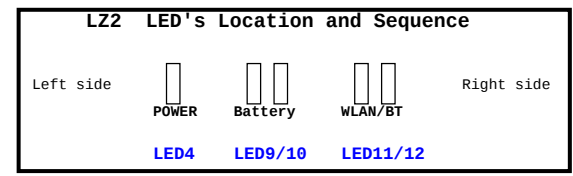
<Variant Name>			
		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
Cantiga(87):GND			
Size A3	Document Number		Rev SB
LZ2			
Date:	Wednesday, April 09, 2008	Sheet	14 of 41



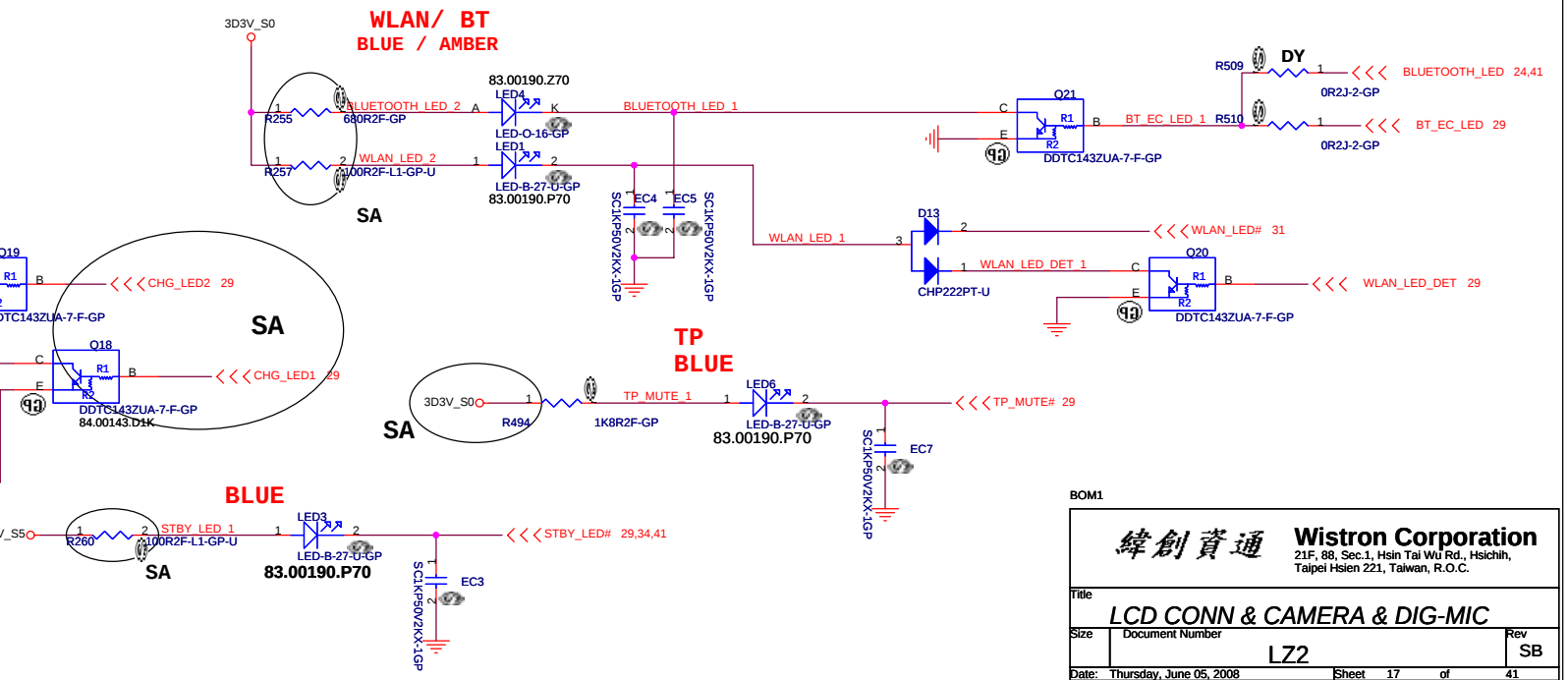
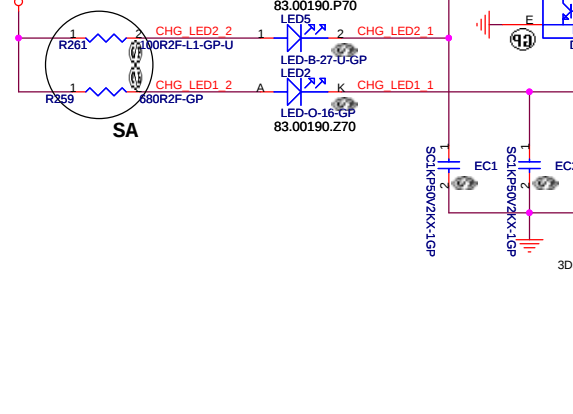




M/B LED

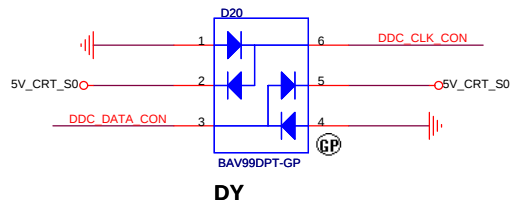
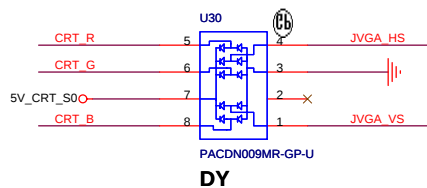
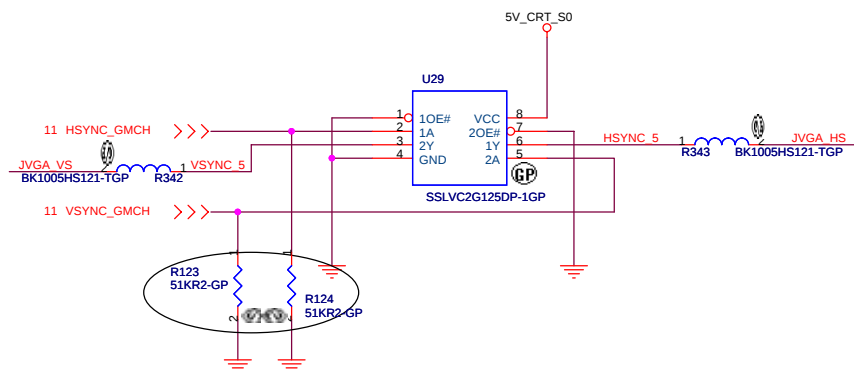
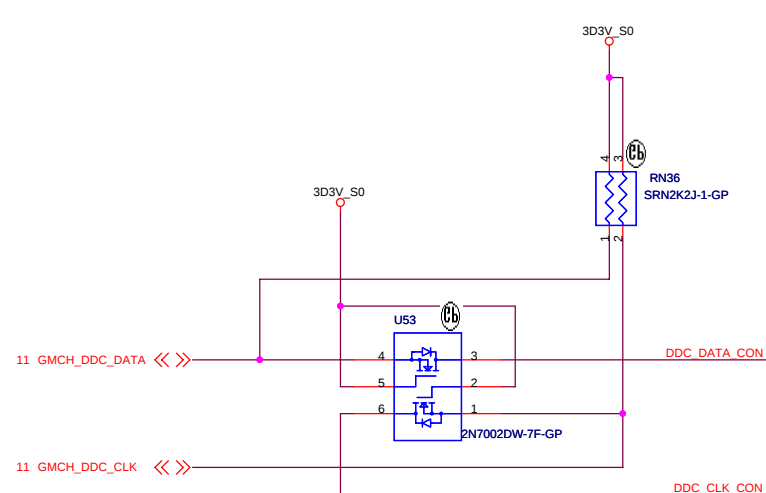
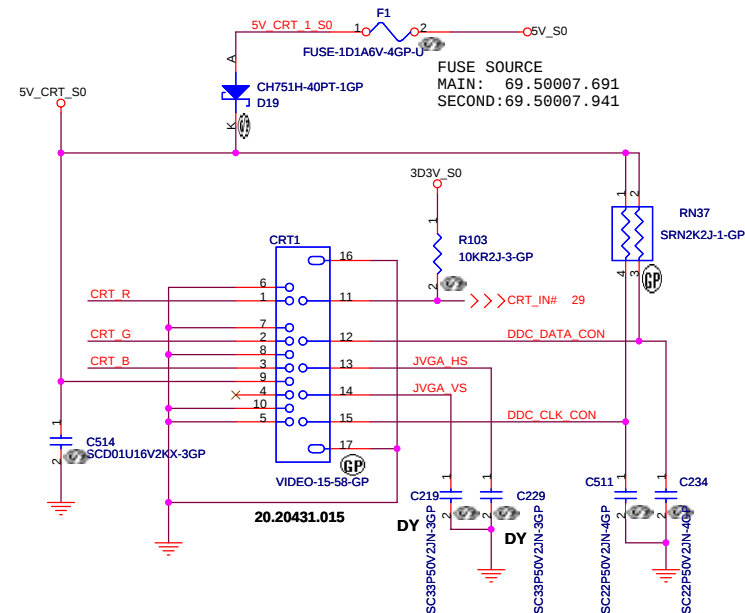
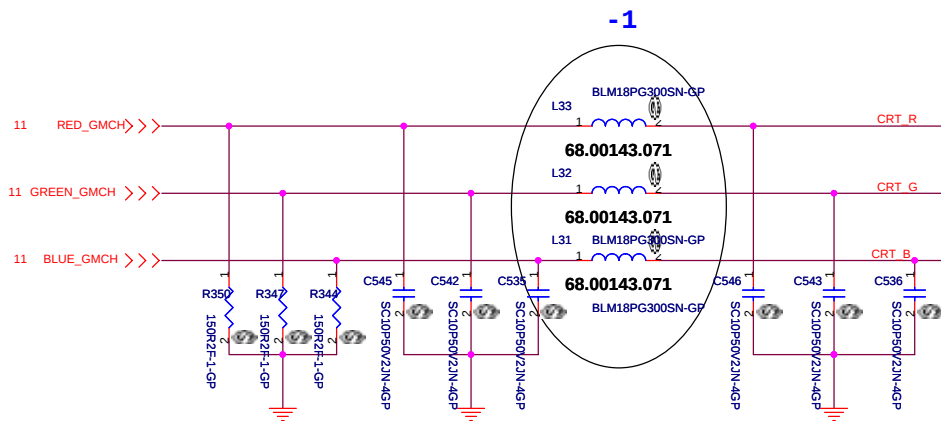


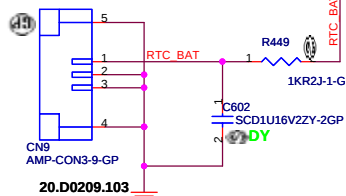
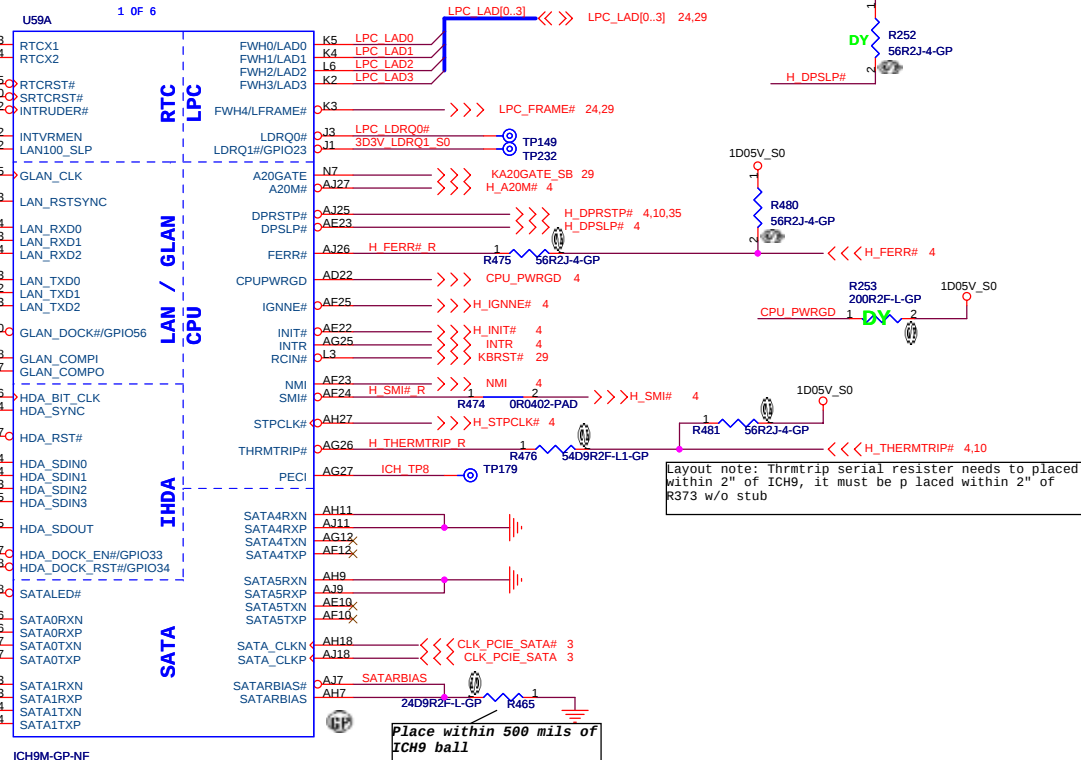
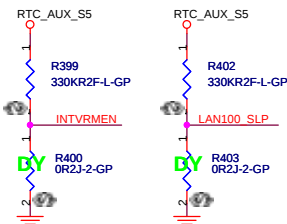
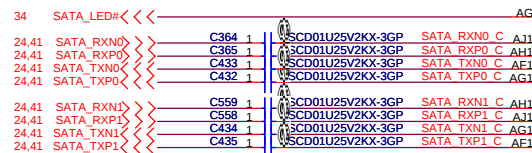
BLUE BAT_USE AMBER CHARGE



BOM1

緯創資通		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
LCD CONN & CAMERA & DIG-MIC			
Size	Document Number		Rev
	LZ2		SB
Date:	Thursday, June 05, 2008	Sheet	17 of 41



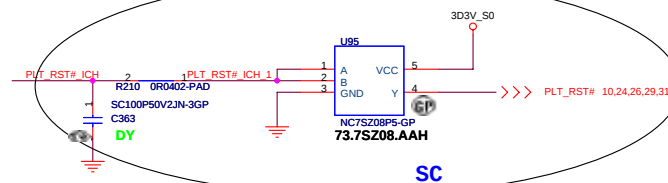
[illegible]

integrated VccSns1_05,VccSns1_5,VccCL1_5	
INTVRMEN	High=Enable Low=Disable
integrated VccLan1_05VccCL1_05	
LAN100_SLP	High=Enable Low=Disable

<Variant Name>

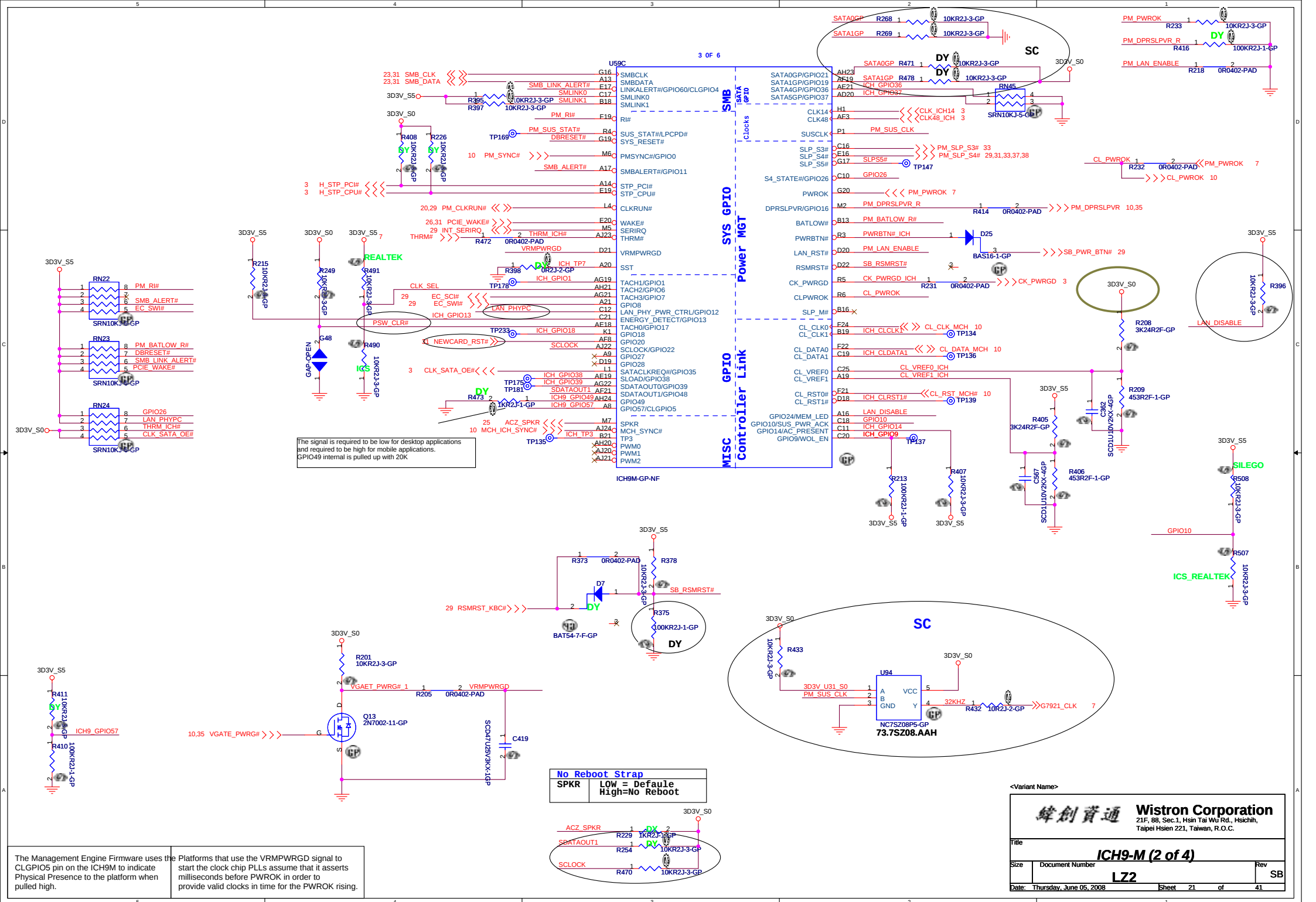
緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title			
ICH9-M (1 of 4)			
Size	Document Number	Rev	SB
	L72		
Date: Thursday, June 05, 2008	Sheet 19	of 41	

[illegible]

B

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Heichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
Size		Document Number	
Date: Thursday, June 05, 2008		Sheet 20 of 41	
L2Z		Rev SB	



The Management Engine Firmware uses the CLGPIO5 pin on the ICH9M to indicate Physical Presence to the platform when pulled high.

No Reboot Strap
SPKR LOW = Default
High=No Reboot

<Variant Name>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title		Rev
ICH9-M (2 of 4)		SB
Size	Document Number	
LZ2		
Date: Thursday, June 05, 2008	Sheet 21	of 41

VccRTC=6uA in G3

Vcc1_5_B=646mA

*Within a given well, 5VREF needs to be up before the corresponding 3.3V rail

VccSATAPLL=47mA

Vcc1_5_A=1.342A

USBPLL=11mA

VccLAN3_3=19mA

VccGLANPLL=23mA

VccGLAN1_5=80mA

VccGLAN3_3=1mA

Vcc1_05=1.634A

Layout Note:Place near ICH9M

VccDMIPLL=23mA

VccDMI=48mA

V_CPU_I0=2mA

VCC3_3=308mA

VccHDA=11mA

VccSusHDA=11mA

VccSus3_3=212mA

VccCL3_3=19mA

緯創資通

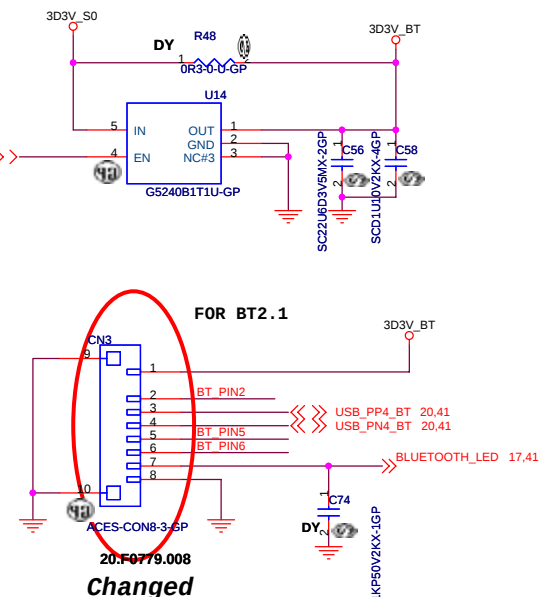
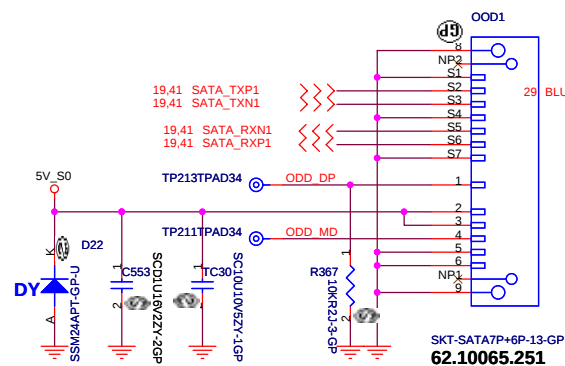
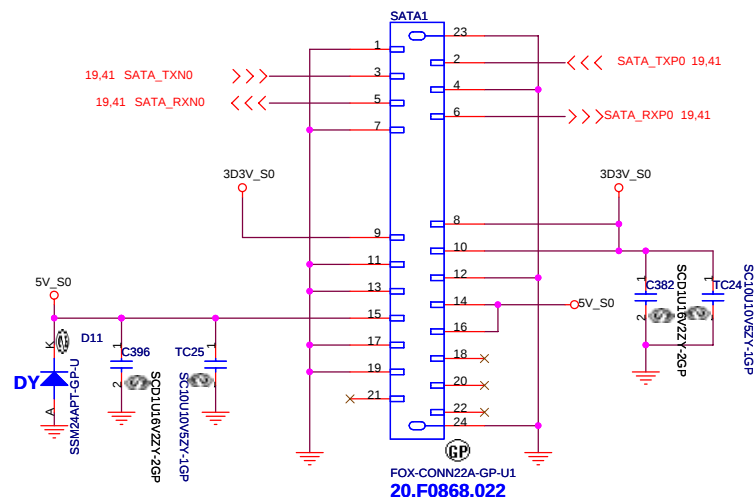
Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

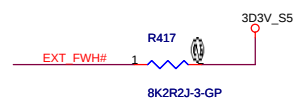
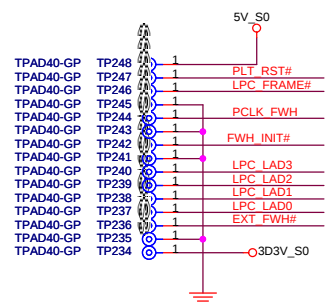
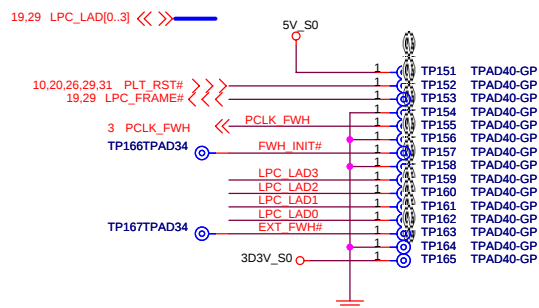
Title			
ICH9-M (3 of 4)			
Size	Document Number		Rev
	LZ2		S
Date: Thursday, May 29, 2008		Sheet 22 of	41

ODD Connector

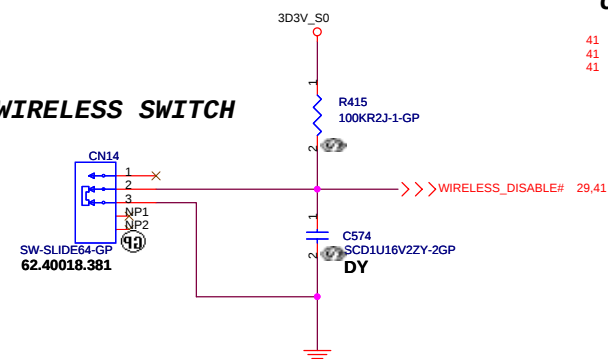
BT CONNECTOR



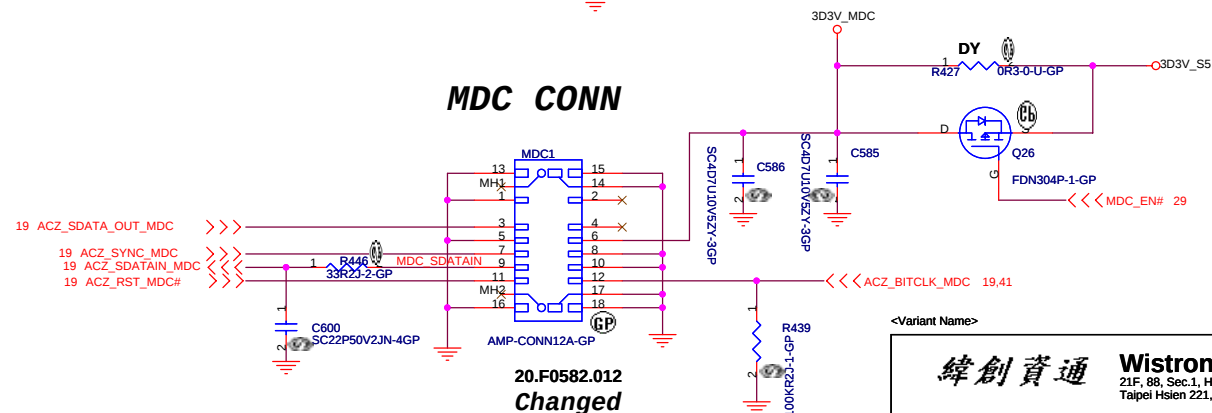
GOLDEN FINGER FOR DEBUG BOARD



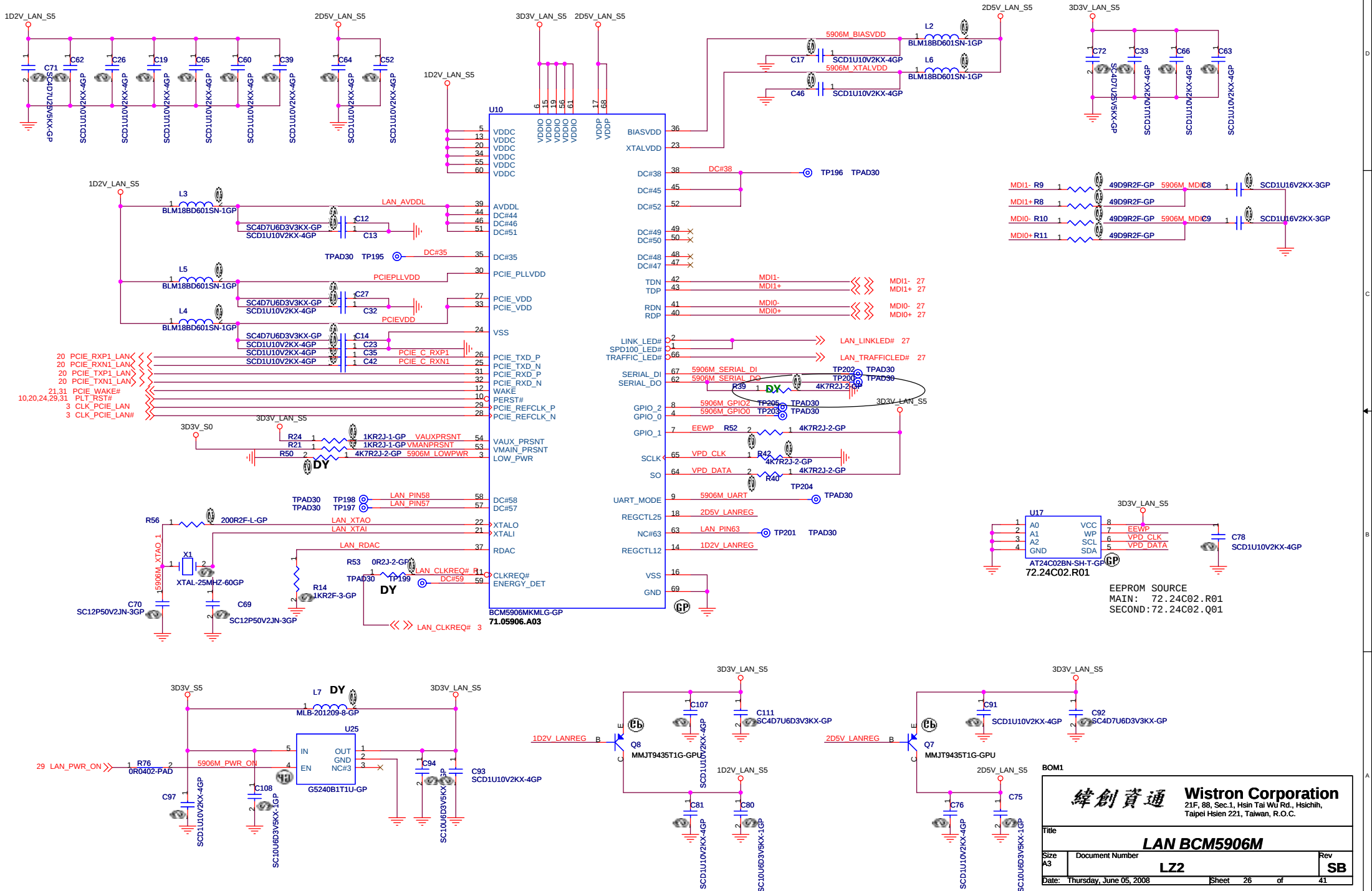
WIRELESS SWITCH



MDC CONN







緯創資通

Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title

LAN BCM5906M

Size

A3

Document Number

LZ2

Rev

SB

Date

Thursday, June 05, 2008

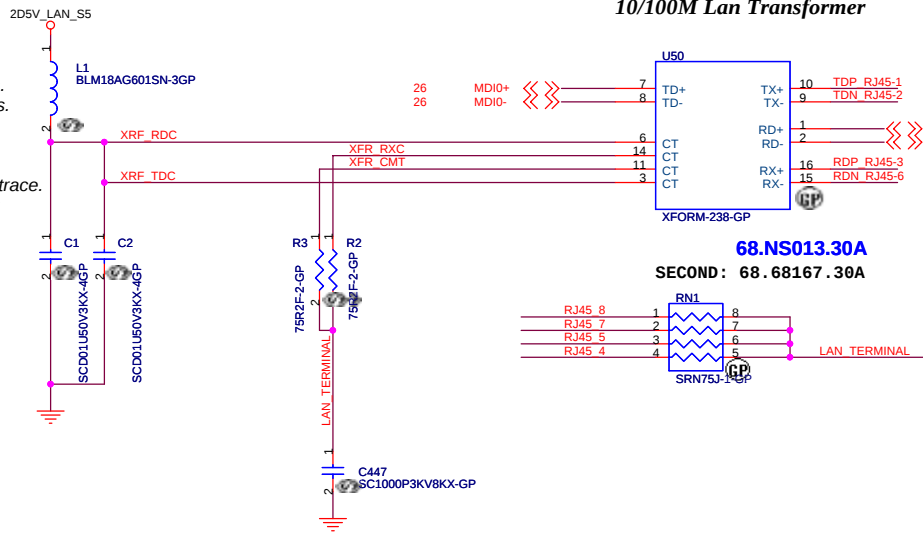
Sheet

26

of

41

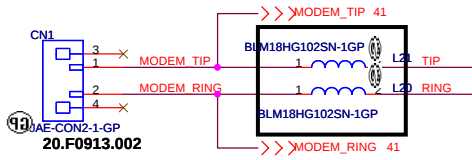
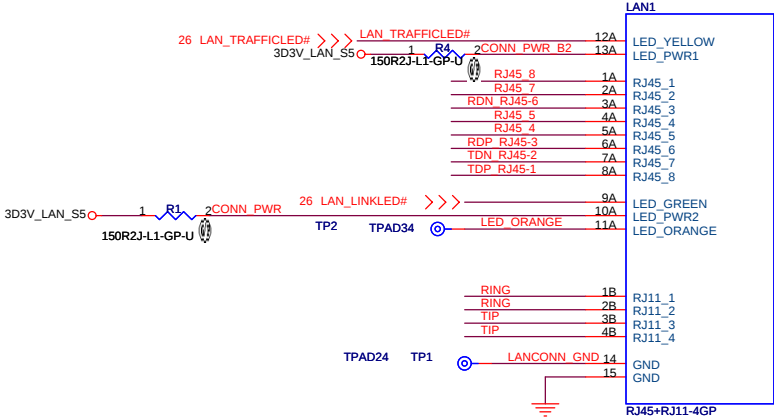
- 1.route on bottom as differential pairs.
2.Tx+/Tx- are pairs. Rx+/Rx- are pairs.
3.No vias, No 90 degree bends.
4.pairs must be equal lengths.
5.6mil trace width,12mil separation.
6.36mil between pairs and any other trace.
7.Must not cross ground moat,except RJ-45 moat.



10/100M Lan Transformer

68.NS013.30A

SECOND: 68.68167.30A

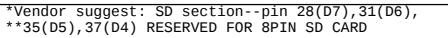


Changed

<Variant Name>

緯創資通 Wistron Corporation		
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title LAN connector/NEW CARD/SIM		
Size A3	Document Number LZ2	Rev SB
Date: Thursday, June 05, 2008 Sheet 27 of 41		

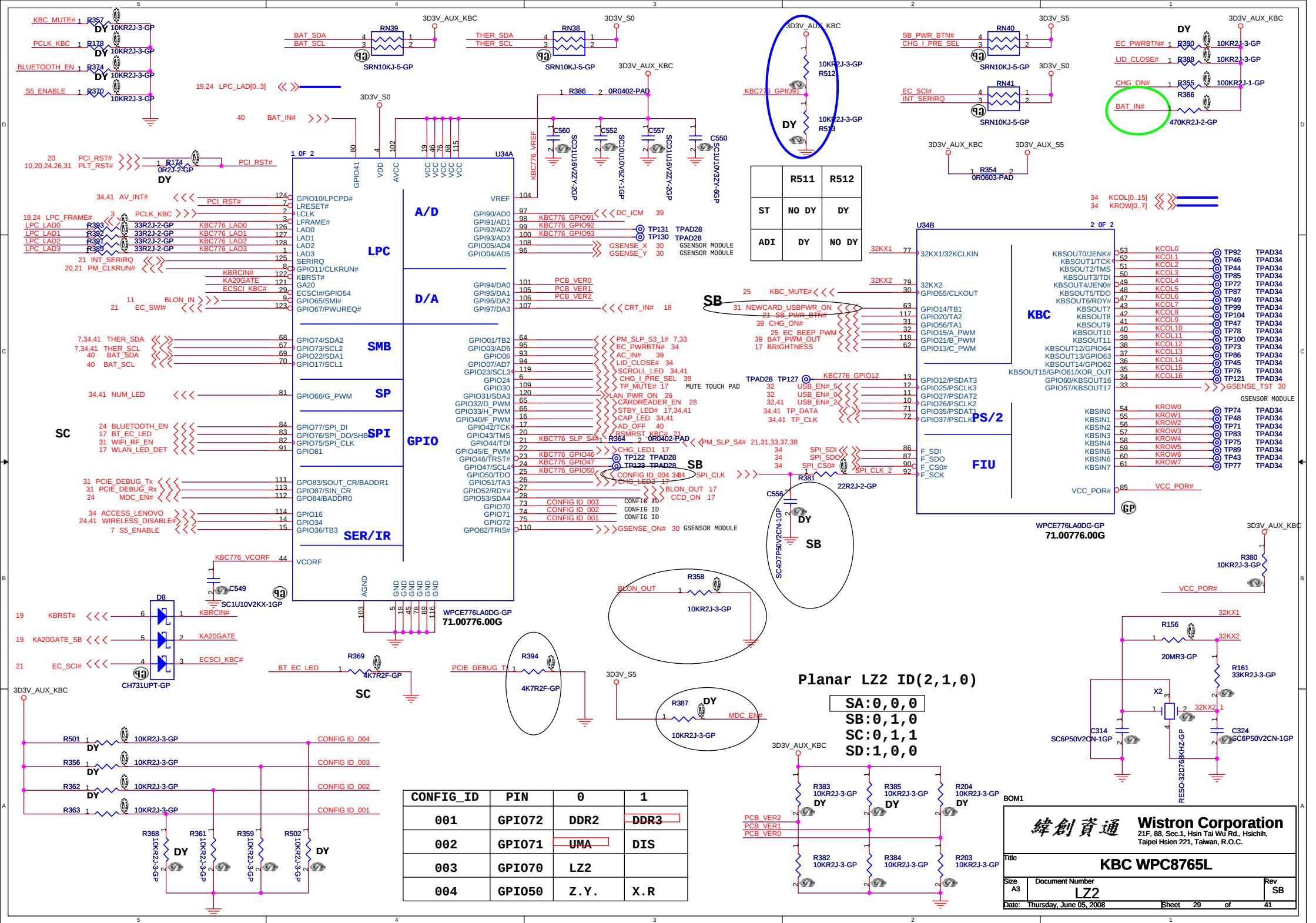
R1302	C38	SD_D1 OUT FROM	IC P/N
10K	47 PF	PIN 26(MS_D1)	5158&5158E
NC	NC	PIN 23	5158E

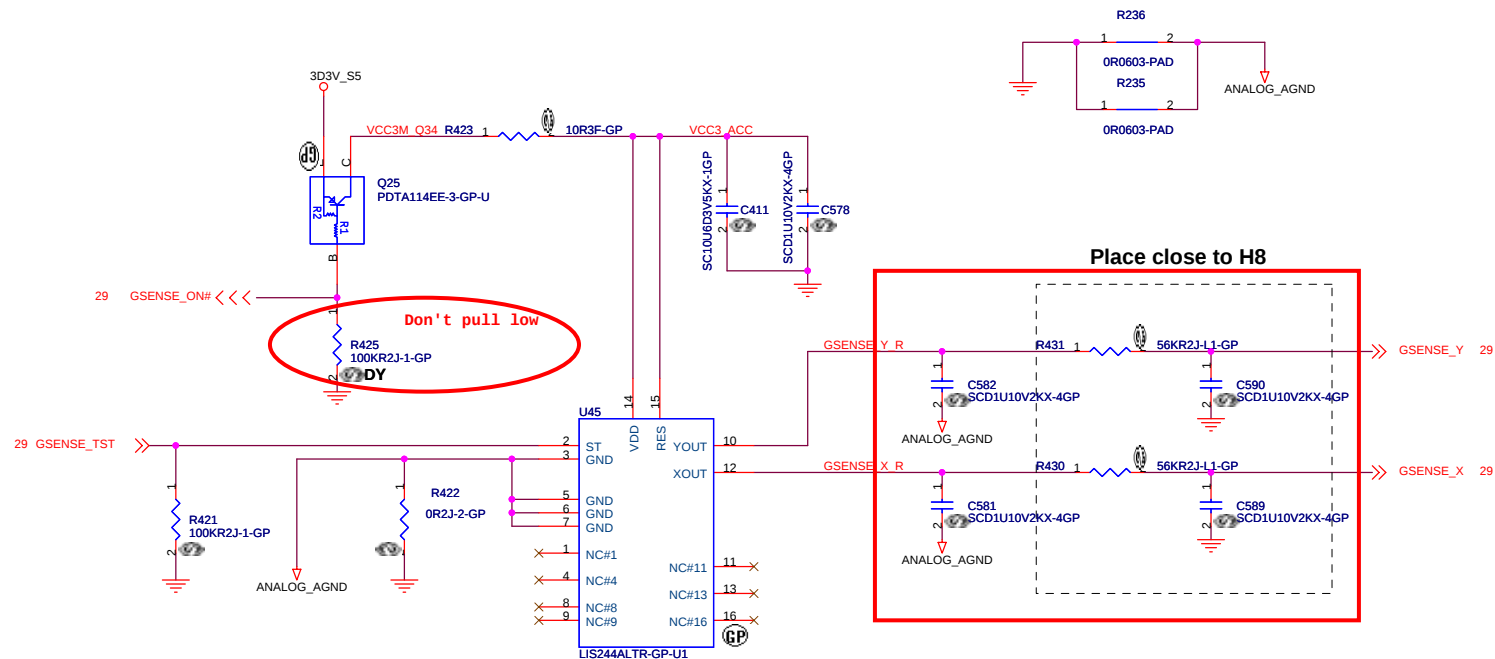


CLK CONTROL	R1303 R1301	X7, R1373, C842, C843
48MHZ	ASM	NO ASM
12MHZ	NO ASM	ASM

Pin 13 (XTAL CTL)	Clock source	Remark
Floating	12MHz crystal input	
Pull high	Clock generator's 48MHz input	Input to RTS5158E(Pin 48)

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title		CARD READER	
Size A3	Document Number	L72	Rev SB
Date: Thursday, June 05, 2008		Sheet 28	of 41





Main :74.00244.0BZ
2nd: 41A1237AA

Width = 6 mil & Spacing = 10 mil
for three Output traces

	ADXL322 LIS244AL	No Accel
R545	NO_ASM	ASM
R547	ASM	ASM
All other	ASM	NO_ASM

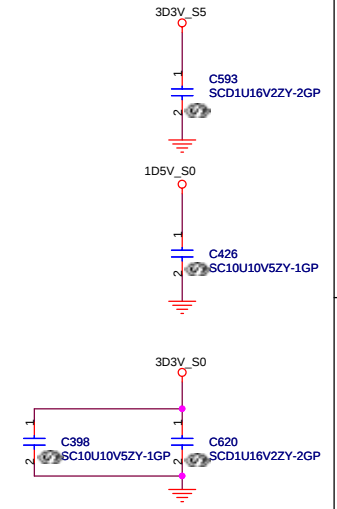
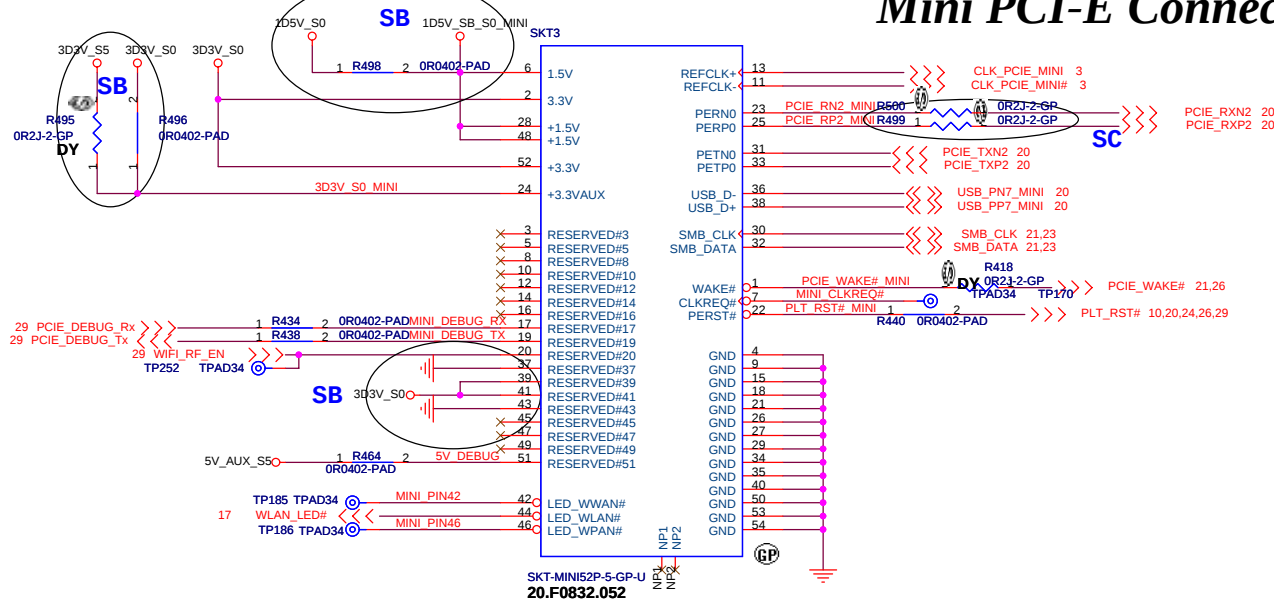
Layout Comment :

- (1) Place C148, C149, Q18, R116, R121, C126, C130, R107, R106 close to U18.
- (2) Avoid routing under DCDC switching area.

BOM1

緯創資通		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
GSENSOR			
Size	Document Number		Rev
	LZ2		SB
Date: Thursday, June 05, 2008		Sheet 30 of 41	

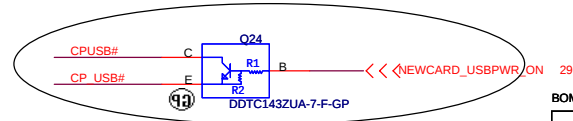
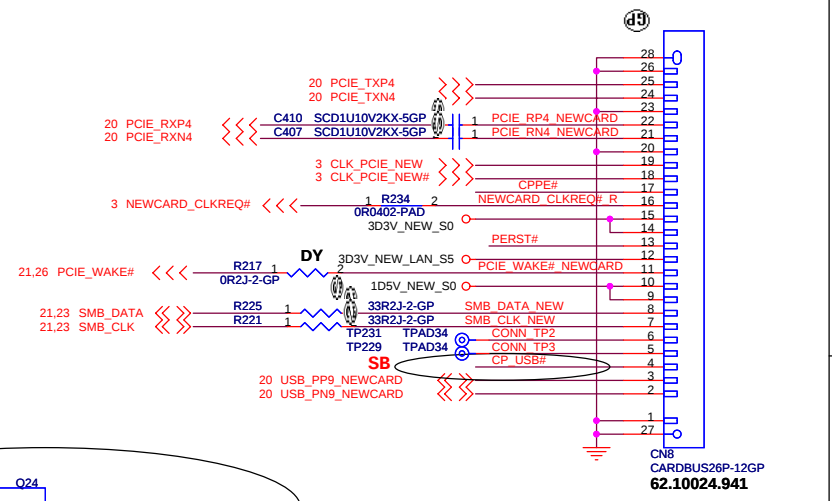
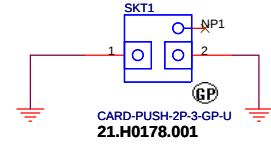
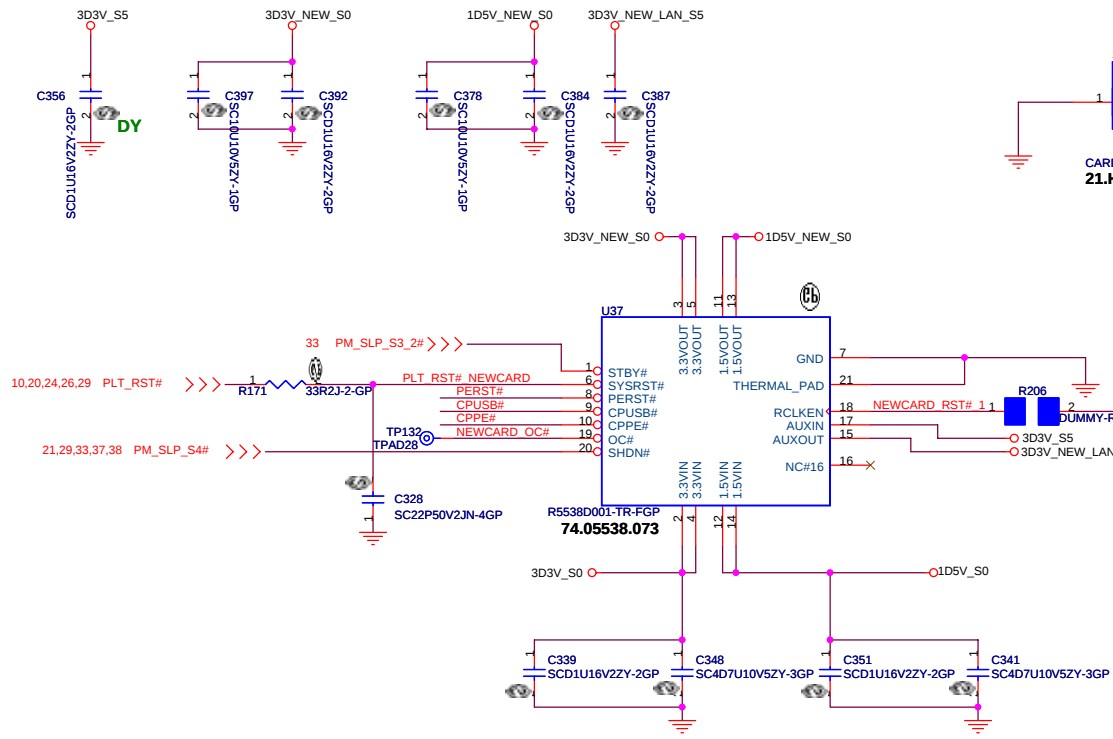
Mini PCI-E Connector



.N.E.W.C.A.R.D. C.O.N.N.

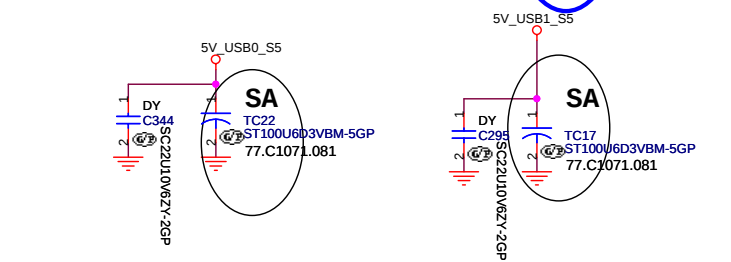
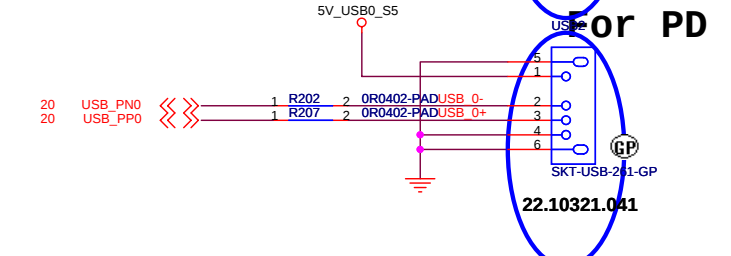
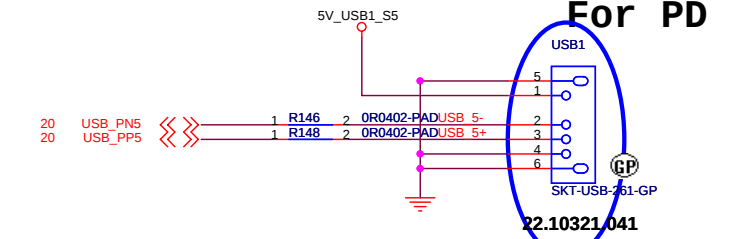
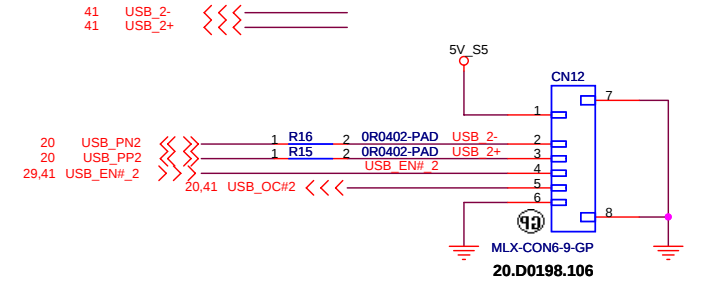
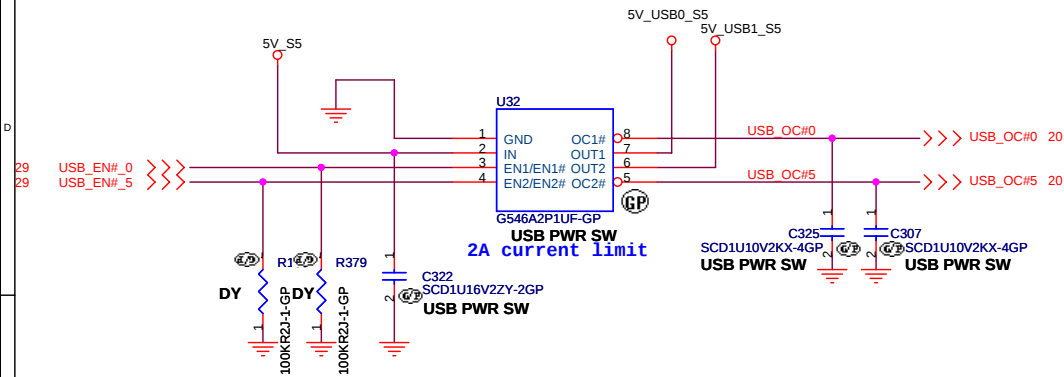
Place them Near to Chip

Place them Near to Connector

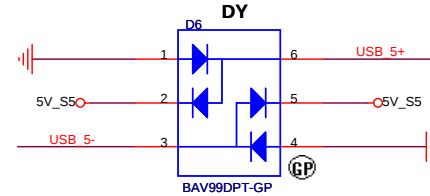
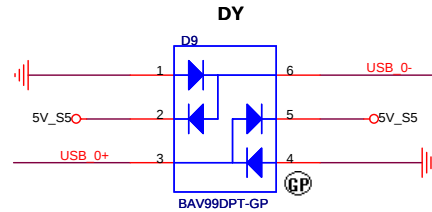
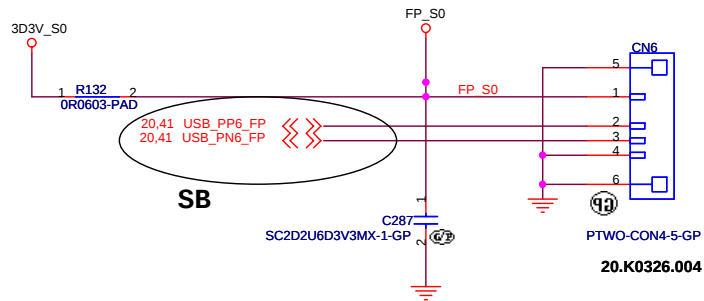


緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
MINI CARD & NEWCARD	
Title: MINI CARD & NEWCARD Size: A3 Date: Thursday, June 05, 2008	Document Number: LZ2 Sheet: 31 of 41 Rev: SB

USB * 3 PORT

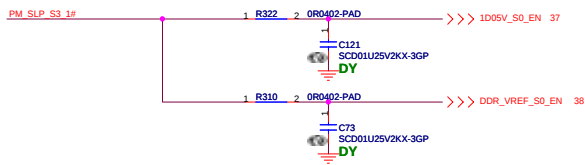
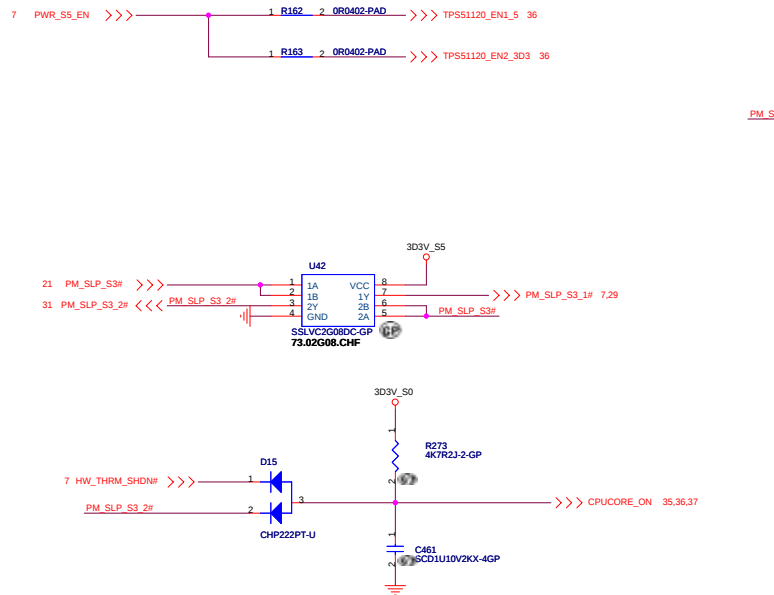


Finger Print

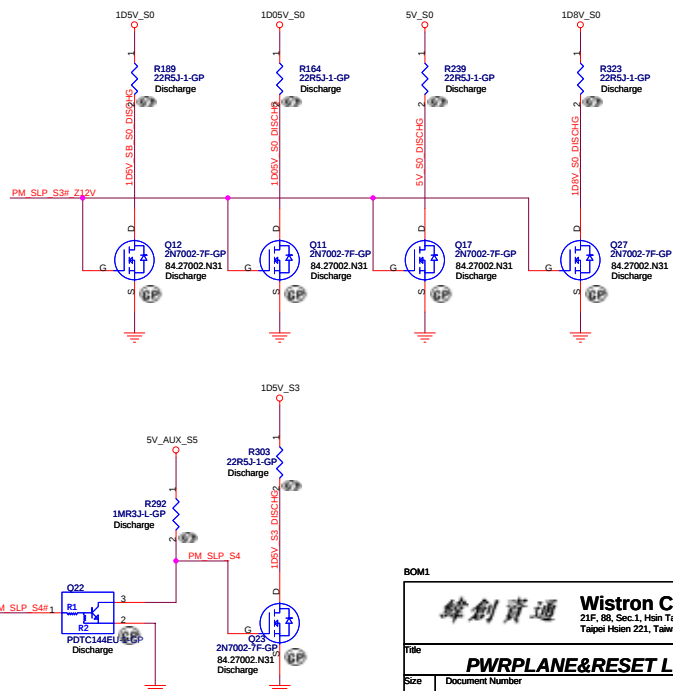
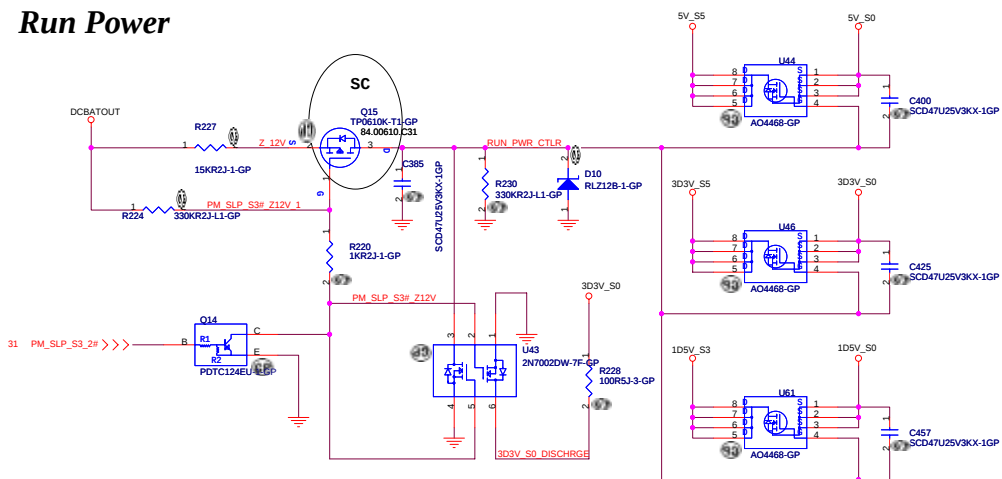


BOM1

緯創資通		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
USB CONN/FINGER PRINT			
Size B	Document Number	LZ2	Rev SB
Date:	Thursday, June 05, 2008	Sheet 32 of	41



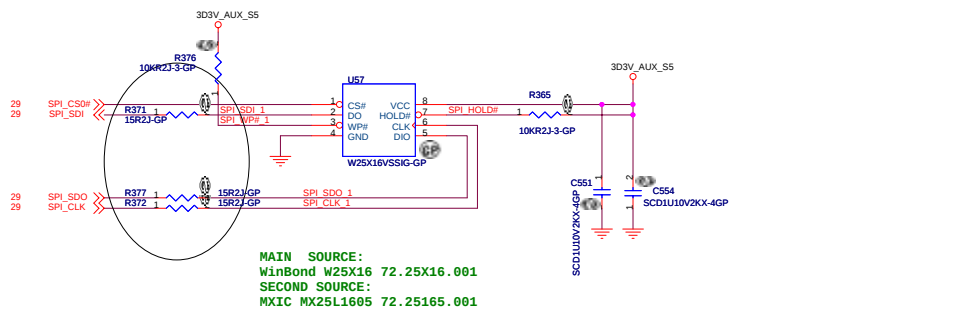
Run Power



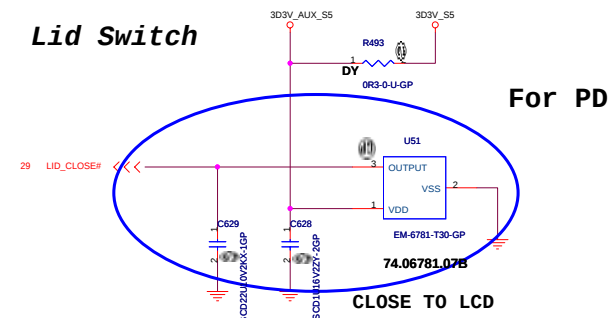
BOM1

Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichia, Taipei Hsien 221, Taiwan, R.O.C.	
Title	PWRPLANE&RESET LOGIC
Size	Document Number
Date	Thursday, June 05, 2008
Sheet	33 of 41
Rev	SB

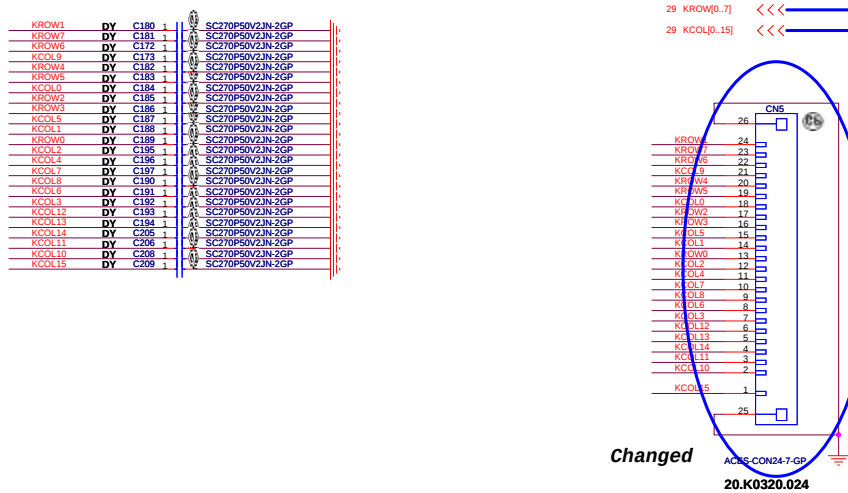
SPI Flash



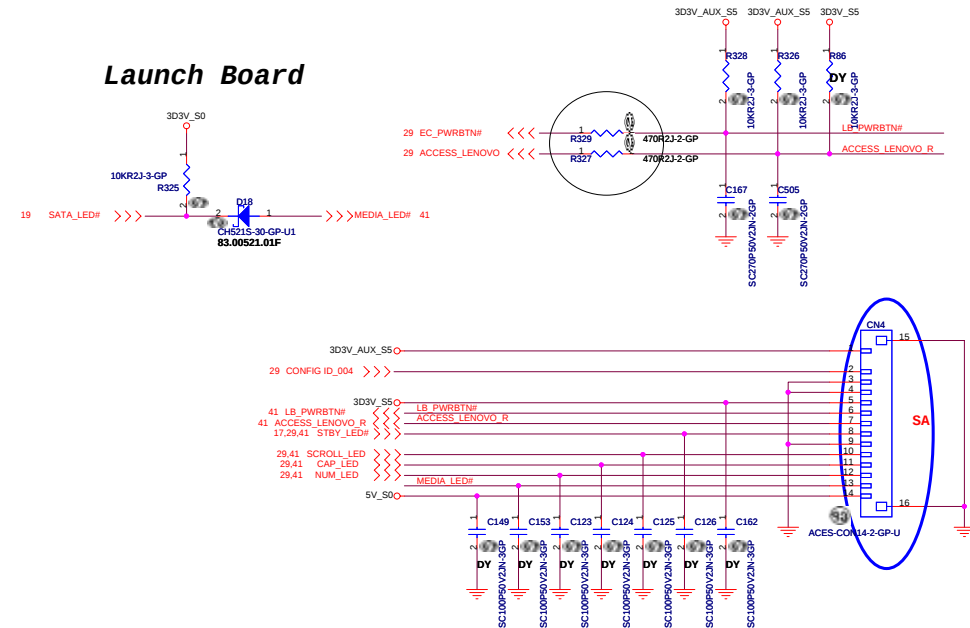
Lid Switch



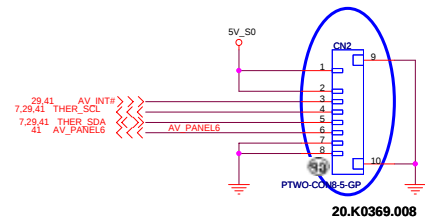
Keyboard Connector



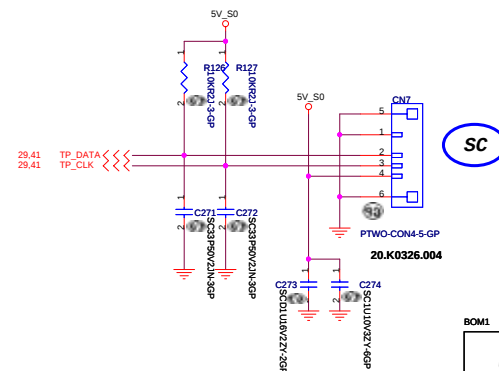
Launch Board

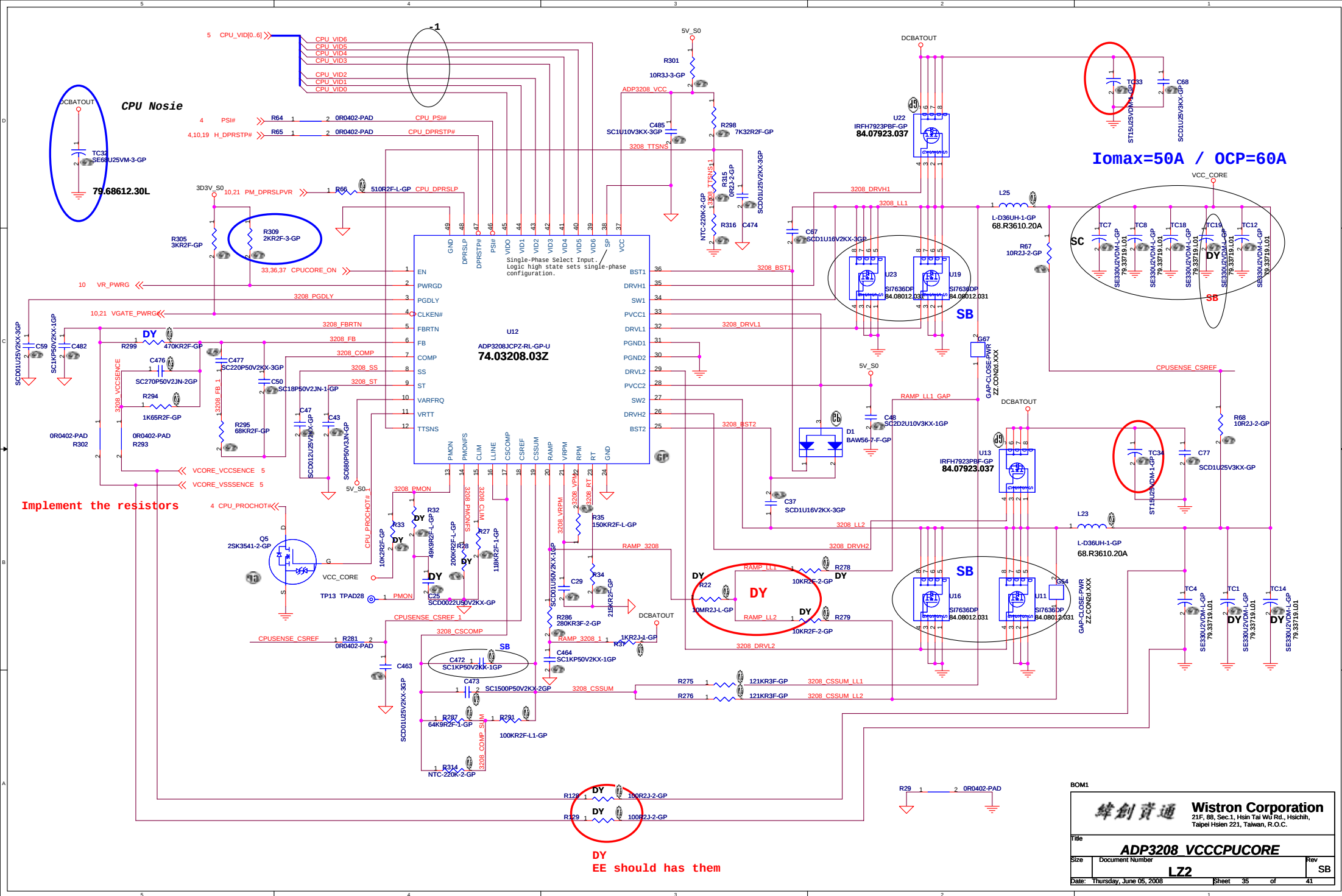


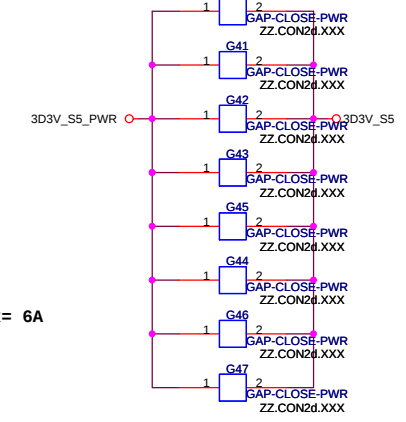
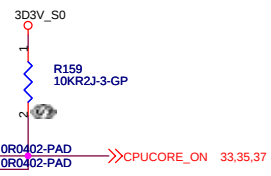
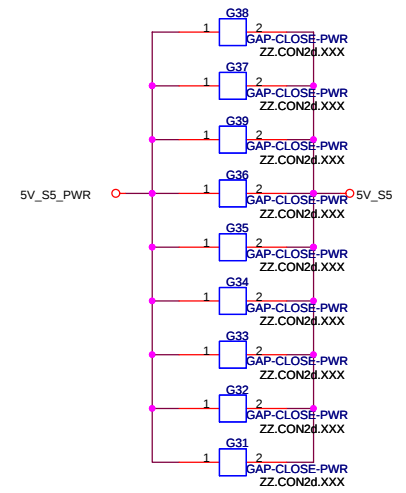
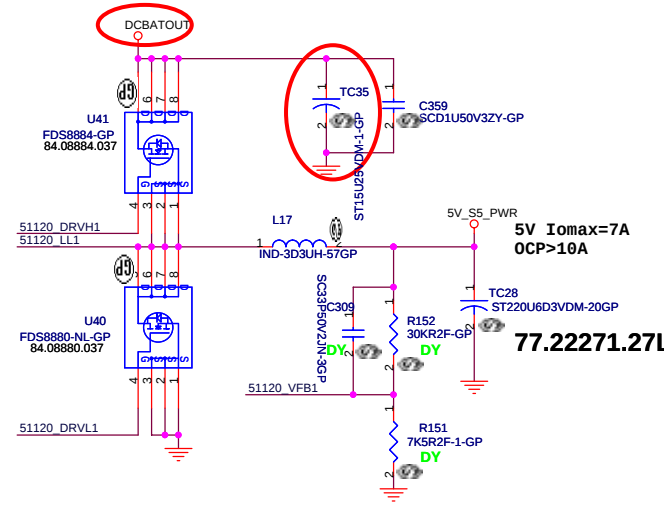
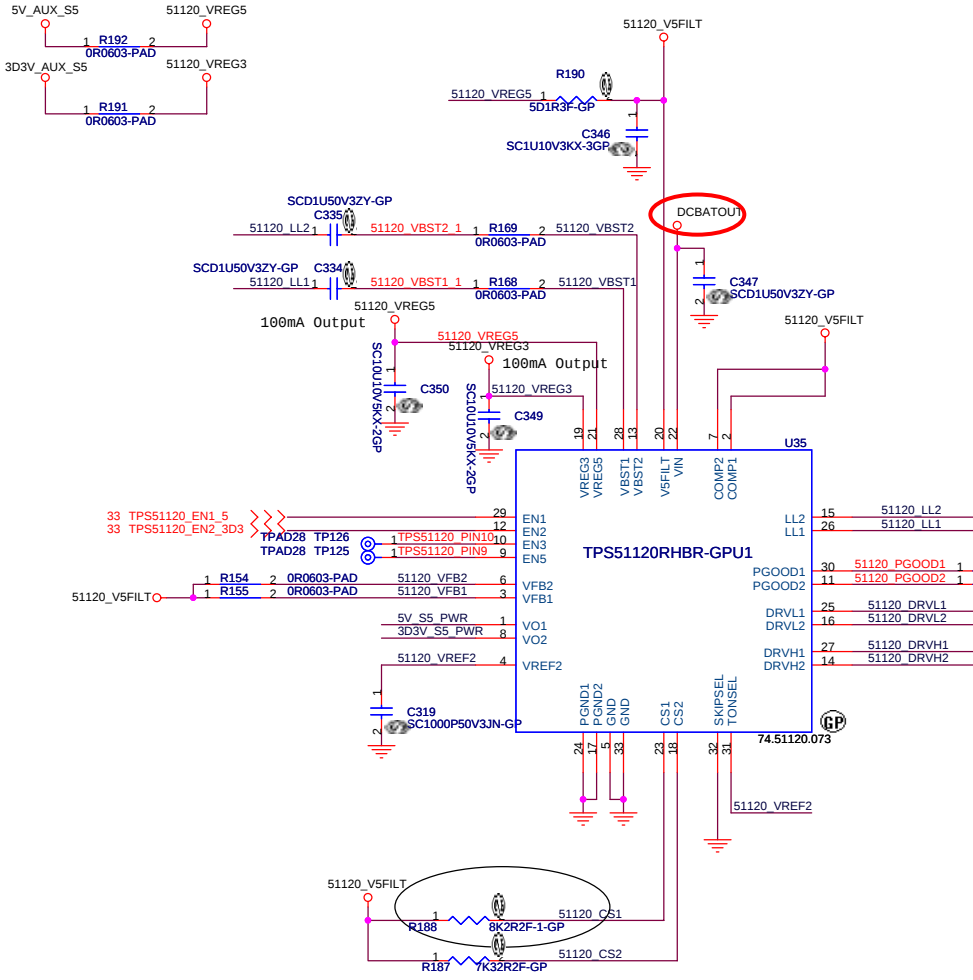
AV Panel



TouchPad Connector







	GND	VREF2	FLOAT	V5FILT
SKIPSEL	AUTOSKIP	AUTOSKIP / FAULTS OFF	PWM	PWM
	N/A	N/A	CURRENT MODE	D-Cap MODE
	380k/CH1 590k/CH2	280k/CH1 430k/CH2	220k/CH1 330k/CH2	180k/CH1 280k/CH2
	N/A	not use	ADJ.	5V Fixed Output
	N/A	not use	ADJ.	3.3V Fixed Output
Switcher OFF	not use	Switcher ON	Switcher ON	Switcher ON
LDO OFF	not use	LDO ON	VREG3 on	VREG3 on

For TPS51120,
Vout=5V

1. If you use a 6.8uH inductor, the minimum ESR is 70m ohm.
2. If you use a 4.7uH inductor, the minimum ESR is 48m ohm.
3. If you use a 3.3uH inductor, the minimum ESR is 34m ohm.

Vout=3.3V

1. If you use a 4.7uH inductor, the minimum ESR is 51m ohm.
2. If you use a 3.3uH inductor, the minimum ESR is 36m ohm.
3. If you use a 2.5uH inductor, the minimum ESR is 27m ohm.

<Core Design>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **TPS51120 5V / 3D3V**

Size A3 Document Number **LZ2** Rev **SB**

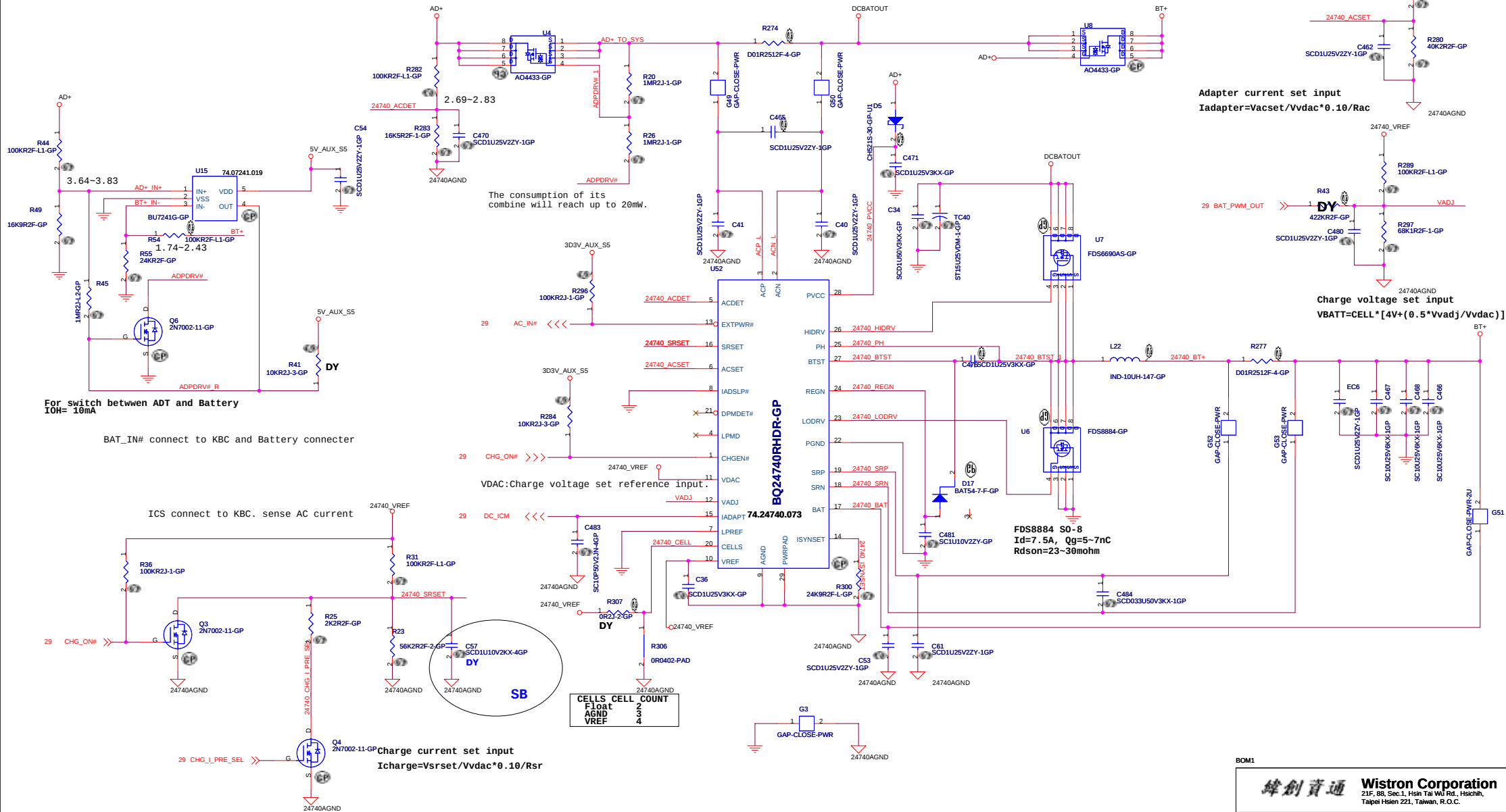
Date: Thursday, June 05, 2008 Sheet 36 of 41

$$V_{out} = 0.758V \cdot (R_1 + R_2) / R_2$$

$$V_{trip}(mV) = R_{trip}(K\Omega) \cdot 10(\mu A)$$

$$I_{ocp} = (V_{trip} / R_{dson}) + ((1 / (2 \cdot L \cdot f)) \cdot ((V_{in} - V_{out}) \cdot V_{out} / V_{in}))$$

CHARGER

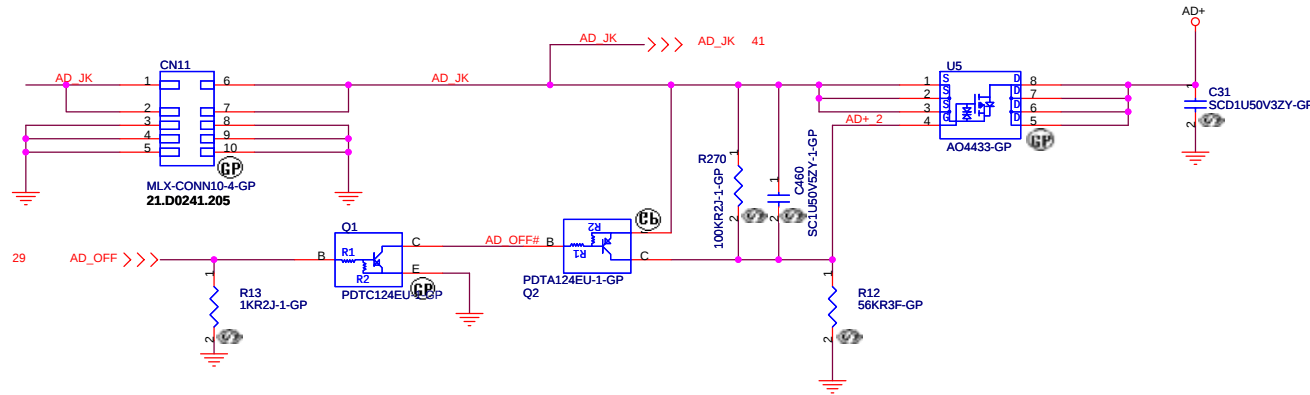


BOM1

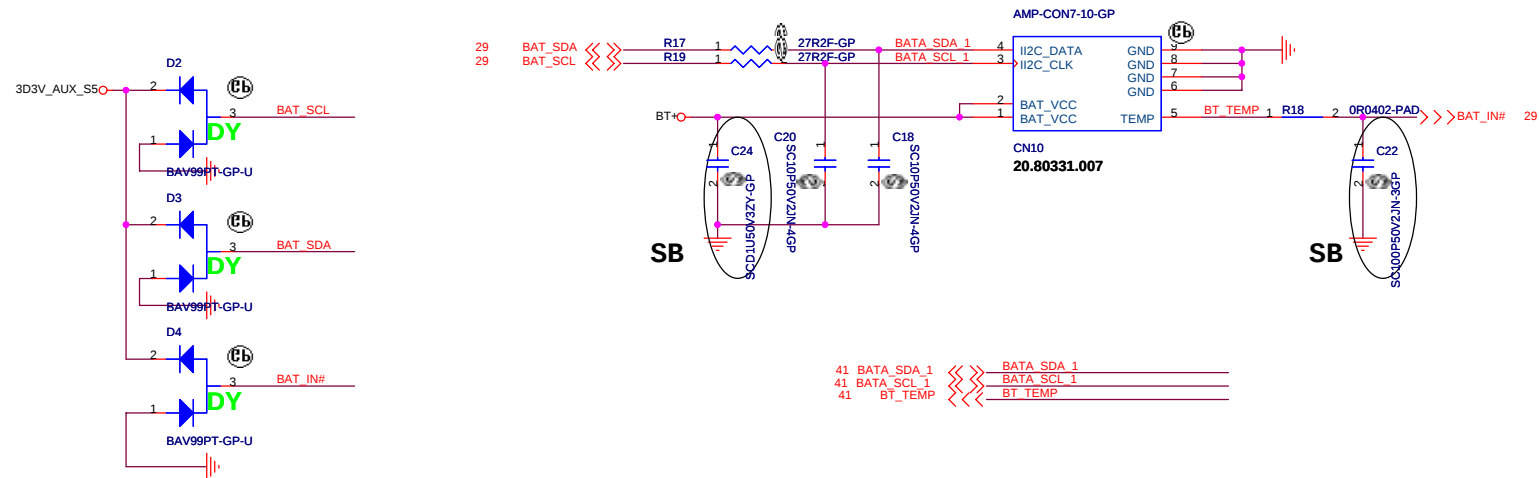
緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title			
Charger BQ24740			
Size	Document Number		Rev
	L72		S
Date:	Thursday, June 05, 2008	Sheet 39 of	41

Adaptor in to generate DCBATOUT



BATTERY CONNECTOR

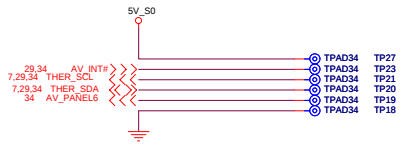


<Core Design>

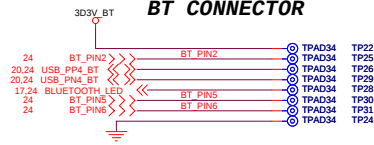
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title		
PTH FOR SCREW HOLES		
Size	Document Number	Rev
A3	LZ2	SB
Date: Thursday, June 05, 2008		
Sheet 40 of 41		

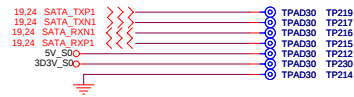
AV Panel



BT CONNECTOR



SATA CONN



TouchPad Connector



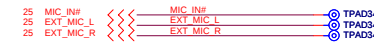
WIRELESS SWITCH



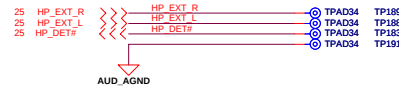
ODD CONN



MIC CONN



HEADPHONE CONN



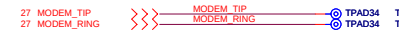
FAN CONN



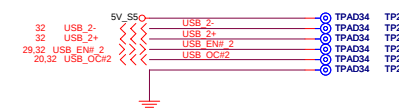
SPEAKER CONN



MODEM CABLE CONN

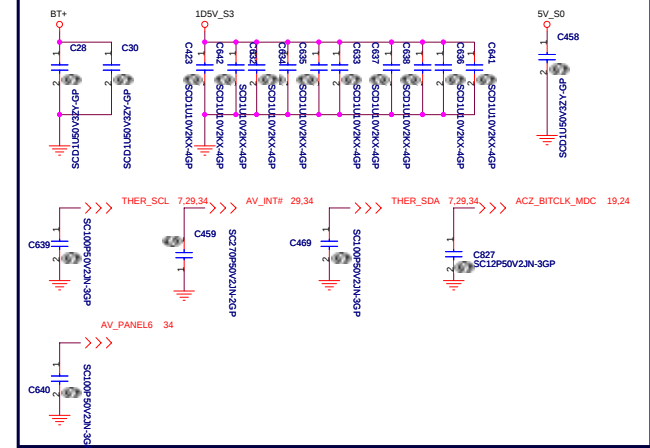


USB BOARD CONN

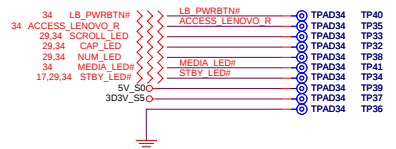


SC

FOR EMI Solution



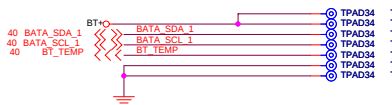
Launch Board



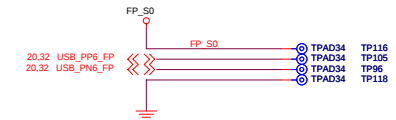
ADT BOARD CONN



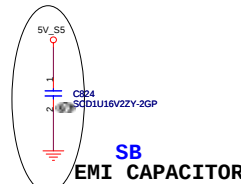
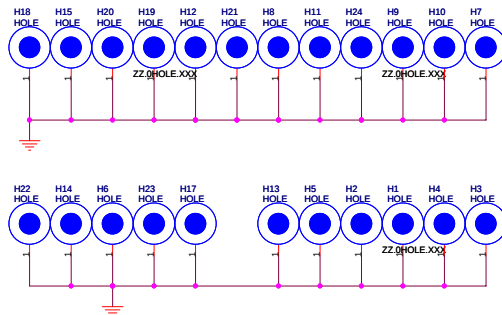
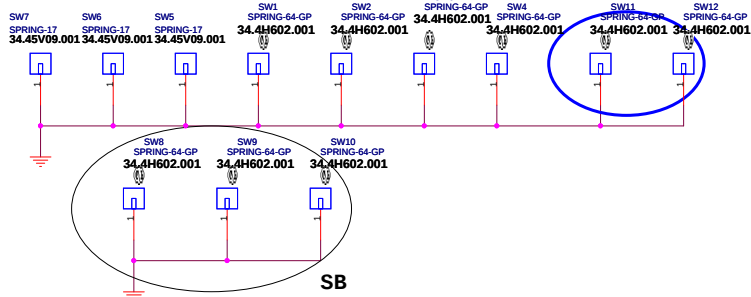
BATTERY CONN



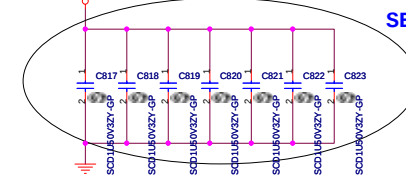
Finger Print CONN



FOR EMI Solution



EMI CAPACITOR



BOM1

Wistron Corporation		
21F, 8B, Sec.1, Hsin Tai Wu Rd., Hsichia, Taipei Hsien 221, Taiwan, R.O.C.		
TTEST_PAD		
File	Document Number	Rev
	LZ2	SB
Date: Thursday, June 05, 2008	Sheet 41 of 41	